



Product Specification

SPECIFICATION FOR APPROVAL

() Preliminary Specification

() Final Specification

Title	14.0" WUXGA TFT LCD
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BUYER		SUPPLIER	LG Display Co., Ltd.
DPN		*MODEL	LP140WU1
		Suffix	SPH2

*When you obtain standard approval,
please use the above model name without suffix

APPROVED BY	SIGNATURE
_____	_____
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_____	_____

Please return 1 copy for your confirmation with your signature and comments.

APPROVED BY	SIGNATURE
_____	_____
REVIEWED BY	
_____	_____
_____	_____
PREPARED BY	
_____	_____

Products Engineering Dept.
LG Display Co., Ltd

Product Specification

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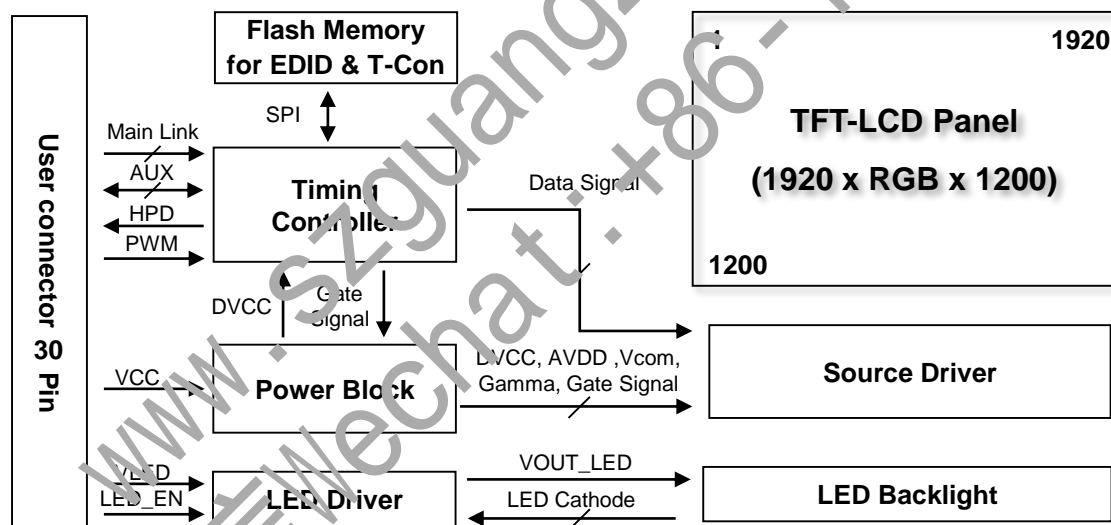
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Product Specification

1. General Description

1-1. Introduction

The LP140WU1 is a Color Active Matrix Liquid Crystal Display with an integral LED backlight system. The matrix employs oxide Thin Film Transistor as the active element. It is a transmissive type display operating in the normally black mode. This TFT-LCD has 14.0 inches diagonally measured active display area with WUXGA resolution (1920 horizontal by 1200 vertical pixel array). Each pixel is divided into Red, Green and Blue sub-pixels or dots which are arranged in vertical stripes. Gray scale or the brightness of the sub-pixel color is determined with a 8-bit gray scale signal for each dot, thus, presenting a palette of 16,777,216 colors. The LP140WU1 has been designed to apply the interface method that enables low power, high speed, low EMI. The LP140WU1 is intended to support applications where thin thickness, low power are critical factors and graphic displays are important. In combination with the vertical arrangement of the sub-pixels, the LP140WU1 characteristics provide an excellent flat display for office automation products such as Notebook PC.



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1-2. General Feature

Active Screen Size		14.0 inches diagonal
Outline Dimension		306.59 (H, Typ.) × 198.40 (V, Typ.) × 1.95 (D, Max.) [mm] (w/o PCB) x 3.95 (D, Max.) [mm] (w/ PCB)
Pixel Pitch		0.1571mm x 0.1571mm
Pixel Format		1920 horiz. by 1200 vert. Pixels RGB strip arrangement
Color Depth		8 bit, 16,777,216 colors
Luminance, White		400cd/m ² (Typ.)
Power Consumption		Total 2.63W (Typ.) Logic : 0.42W (Typ. @ Mosaic), B/L : 2.21W (Typ.) Total 2.75W (Max.) Logic : 0.45W (Max. @ Mosaic), B/L : 2.30W (Max.)
Weight		170g (Max.)
Display Operating Mode		Normally black
Surface Treatment		Anti glare treatment (3H) of the front Polarizer
Color Gamut(Based on CE 1931)		sRGB Typ. 100%, Min 95% (Cover. Ratio)
LED Dimming Control mode		DC Dimming
RoHS Compliance		Yes
BFR / PVC / As Free		Yes for all
eDP version(Tcon)		eDP1.4b
DPCD version		Ver1.4
Function	PSR	PSR2 support
	sDRRS	Not support
	DMRRS	Not support
	Adaptive sync	LRR2.5(48~60Hz)
	NVSF	Not support
	SSC	Down spread 0.5%
	NVIDIA DDS	Not support
	DSC	Not support
	Logos on	Not support
	HDR	Not support
	Intel COT	UBRR, PixOptiX

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2. Absolute Maximum Ratings

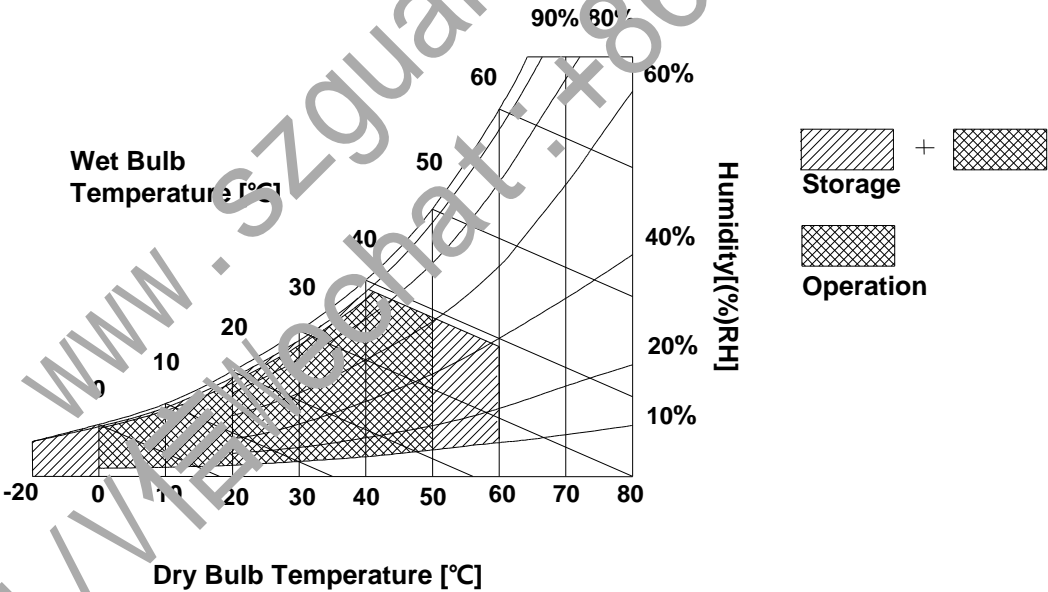
The following are maximum values which, if exceeded, may cause faulty operation or damage to the unit.

Table 1. ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Values		Units	Notes
		Min	Max		
Power Input Voltage	VCC	-0.3	4.0	V _{CC}	at 25 ± 2°C
Operating Temperature	TOP	0	50	°C	1
Storage Temperature	TST	-20	60	°C	1,2
Operating Ambient Humidity	HOP	10	90	%RH	1
Storage Humidity	HST	10	90	%RH	1,2

Note : 1. Temperature and relative humidity range are shown in the figure below.
 Wet bulb temperature should be 39°C Max and no condensation of water.

Note : 2. Storage Condition is guaranteed under packing condition





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3. Electrical Specifications

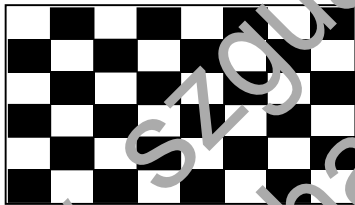
3-1. LCD Electrical Characteristics

Table 2. LCD ELECTRICAL CHARACTERISTICS

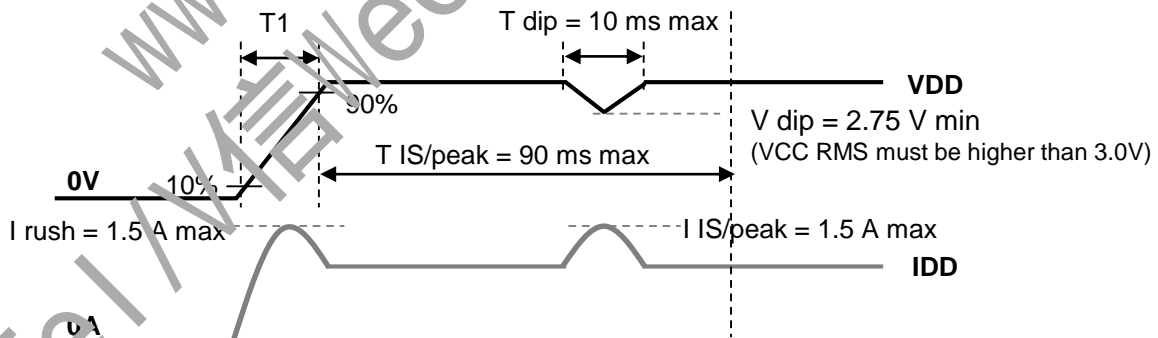
Parameter		Symbol	Values			Unit	Notes
			Min	Typ	Max		
Power Supply Input Voltage		V _{CC}	3.0	3.3	3.6	V	1
Permissive Power Supply Input Ripple		V _{CCrp}	-	-	100	mV _{p-p}	
Power Supply Input Current	Mosaic	I _{CC}	-	127	136	mA	2
	R/G/B	I _{CC}	-	127	136	mA	
Power Consumption	Mosaic	P _{CC}	-	0.42	0.45	W	
	R/G/B	P _{CC}	-	0.42	0.45	W	
Power Supply Inrush Current		I _{CC_P}	-	-	5	A	3
Differential Impedance		Z _{eDP}	72.3	85	97.8	Ω	

Note)

1. The measuring position is the connector of LCM and the test conditions are under 25°C, f_v = 60Hz
2. The specified I_{CC} current and power consumption are under the v_{CC} = 3.3V, 25°C, f_v = 60Hz condition and Mosaic / RGB pattern.



3. The V_{CC} rising time & V_{CC} Dip condition



Definition :

- V dip : VDD drop voltage after power on
- T dip : the duration time of V dip
- T IS/peak : maximum current occurring time after power on
- I IS/peak : maximum current in T I_{max}

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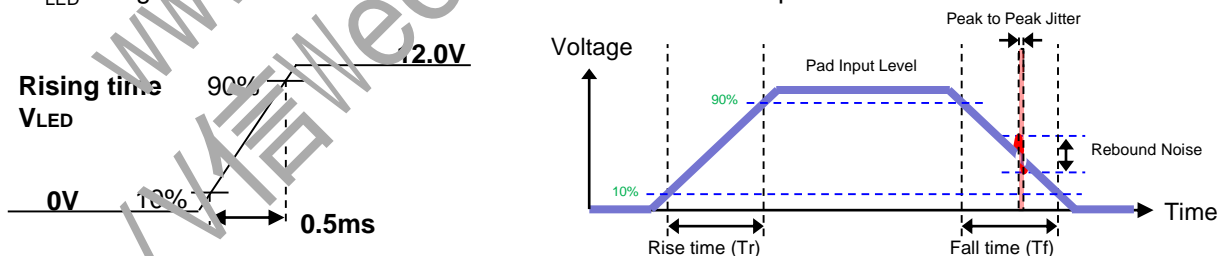
3-2. LED Backlight Electrical Characteristics

Table 3. LED B/L ELECTRICAL CHARACTERISTICS

Parameter		Symbol	Values			Unit	Notes
			Min	Typ	Max		
LED Power Input Voltage		V_{LED}	5.0	12.0	21.0	V	1
LED Power Input Current		I_{LED}	-	184	192	mA	2
LED Power Consumption		P_{LED}	-	2.21	2.30	W	3
LED Power Inrush Current		I_{LED_P}	-	-	1.5	A	4
PWM Duty Ratio			5	-	100	%	4
PWM Resolution				10		Bit	5
PWM Jitter			0	-	0.05	%	6
PWM Frequency		F_{PWM}	200	-	2000	Hz	7
PWM	High Level Voltage	V_{PWM_H}	2.5	-	3.6	V	
	Low Level Voltage	V_{PWM_L}	0	-	0.3	V	
	Tr / Tf @ 200Hz		-	-	25/25	us	
	Tr / Tf @ 2Khz		-	-	2.5/2.5	us	
	P to P Jitter @ 200hz		-	-	1	us	8
	P to P Jitter @ 2Khz		-	-	0.1	us	
LED_EN	High Voltage	$V_{LED_EN_H}$	2.5	-	3.6	V	
	Low Voltage	$V_{LED_EN_L}$	0	-	0.3	V	
Life Time			15,000	-	-	Hrs	9

Note)

1. The measuring position is the connector of LCM and the test conditions are under 25°C.
2. The current and power consumption with LED Driver are under the $V_{LED} = 12.0V$, 25°C, PWM Duty 100% and White pattern with the normal frame frequency operated(60Hz).
3. The V_{LED} rising time is same as the minimum of T13 at Power on sequence.



4. The operation of LED Driver below minimum dimming ratio may cause flickering or reliability issue.
5. 10bit resolution means it's possible to change PWM duty by 0.1% step. (8bit operated by 0.4% step)
6. If Jitter of PWM is bigger than maximum, it may induce flickering.
7. This Spec. is not effective at 100% dimming ratio as an exception because it has DC level equivalent to 0Hz. In spite of acceptable range as defined, the PWM Frequency should be fixed and stable for more consistent brightness control at any specific level desired.
8. PWM rebound spec $\leq 0.1V$
9. The life time is determined as the time at which brightness of LCD is 50% compare to that of minimum value specified in table 7. under general user condition.

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3-3. Interface Connections

Table 4. MODULE CONNECTOR PIN CONFIGURATION (CN1)

Pin	Symbol	Description	Notes
1	DBC	Dynamic Backlight Control (Panel FW : Disabled)	[Connector] I-FLEX 20696-030E-02 (30pin, 0.4pitch)
2	GND	High Speed Ground	
3	Lane1_N	Complement Signal Link Lane 1	
4	Lane1_P	True Signal Link Lane 1	
5	GND	High Speed Ground	
6	Lane0_N	Complement Signal Link Lane 0	
7	Lane0_P	True Signal Link Lane 0	
8	GND	High Speed Ground	
9	AUX_CH_P	True Signal Auxiliary Channel	
10	AUX_CH_N	Complement Signal Auxiliary Channel	
11	GND	High Speed Ground	[Connector pin arrangement] Pin 30 Pin 1
12	VCC	LCD logic and driver power (Typ. 3.2V)	
13	VCC	LCD logic and driver power (Typ. 3.3V)	
14	BIST	Built in Self Test (Typ. 3.3V)	
15	GND	LCD logic and driver ground	
16	GND	LCD logic and driver ground	
17	HPD	HPD signal pin (Typ. 3.3V)	
18	BL_GND	LED Backlight ground	
19	BL_GND	LED Backlight ground	
20	BL_GND	LED Backlight ground	
21	BL_GND	LED Backlight ground	[LGD I2C using information] 1.Pin for P-Vcom : #24, #25 2.P-Vcom Address : TBD 3.PMIC control Address : TBD 4.LED IC control Address : TBD
22	BL ENABLE	LED Backlight control on/off control (Typ. 3.3V)	
23	BL PWM	System PWM signal input for dimming (Typ. 3.3V)	
24	NC Reserved	Reserved for LCD manufacture's use	
25	NC Reserved	Reserved for LCD manufacture's use	
26	VLED	LED Backlight power (Typ. 12V)	
27	VLED	LED Backlight power (Typ. 12V)	
28	VLED	LED Backlight power (Typ. 12V)	
29	VLED	LED Backlight power (Typ. 12V)	
30	NC Reserved	Reserved for LCD manufacture's use	

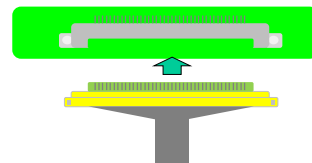


Figure1.HPD Output circuit is as below

Figure1.HPD Output circuit is as below

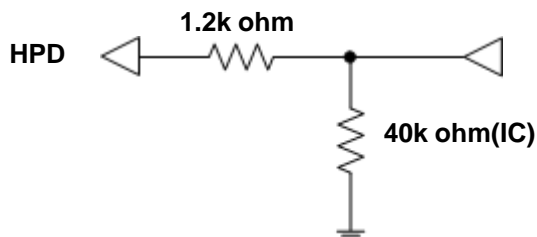


Figure2.BL PWM input circuit is as below

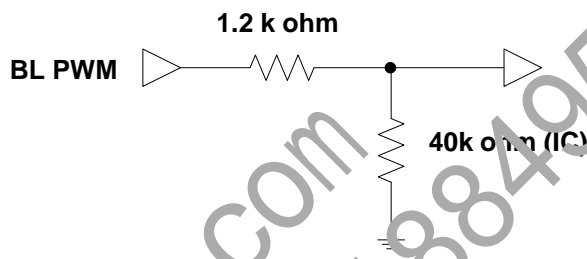


Figure3.BL Enable input circuit is as below

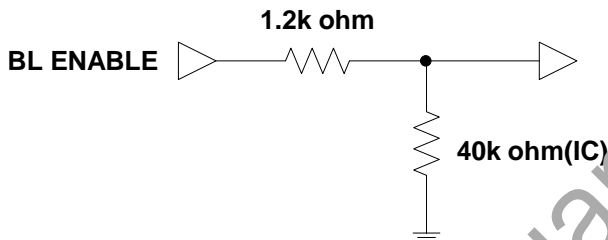


Figure 4.B15 Input circuit is as below

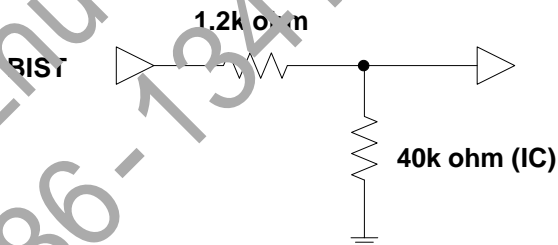


Figure5.DBC input circuit is as below

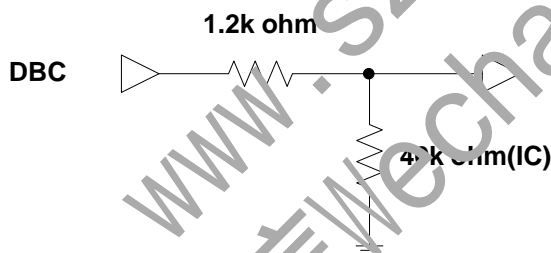
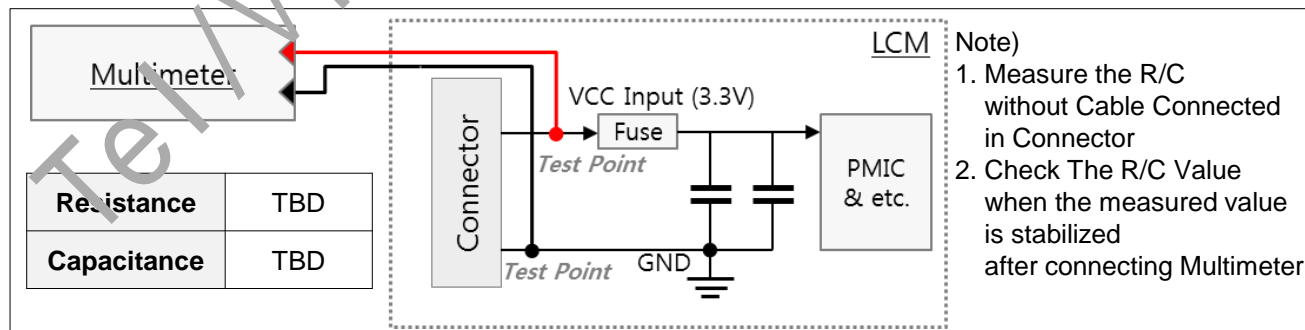


Figure6. R/C Loading Parameter in VCC Loop

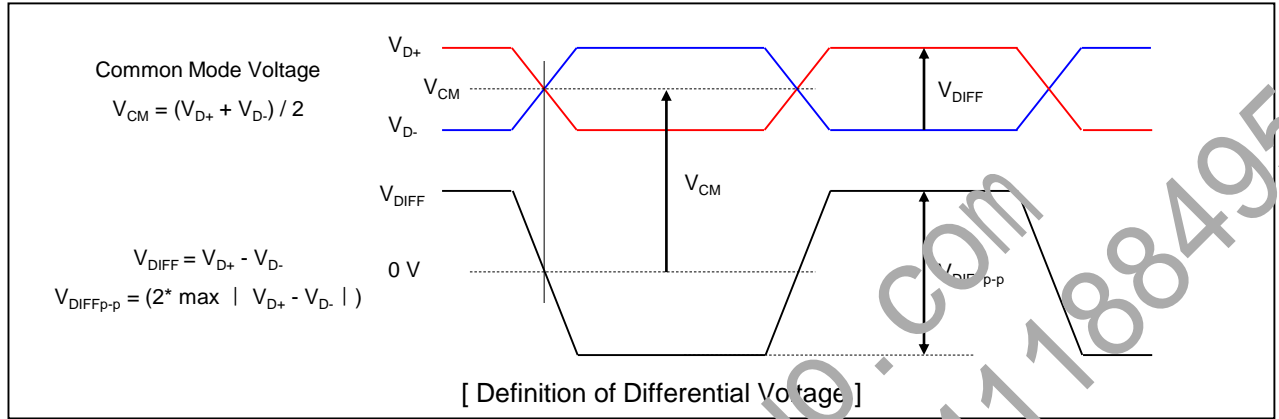




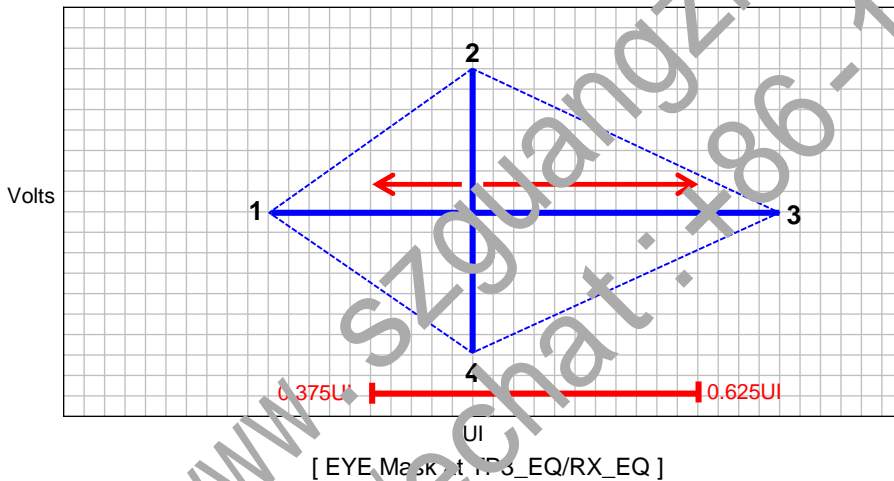
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3-4. eDP Signal Timing Specifications

3-4-1. Definition of Differential Voltage



3-4-2. Main Link EYE Diagram



Point	Time(UI)	Voltage(V)
1	Any UI location (0mV)	0.000
2	0.375<point2<0.625	0.0375
3	Point1 + 0.5UI	0.000
4	0.375<point4<0.625	-0.0375

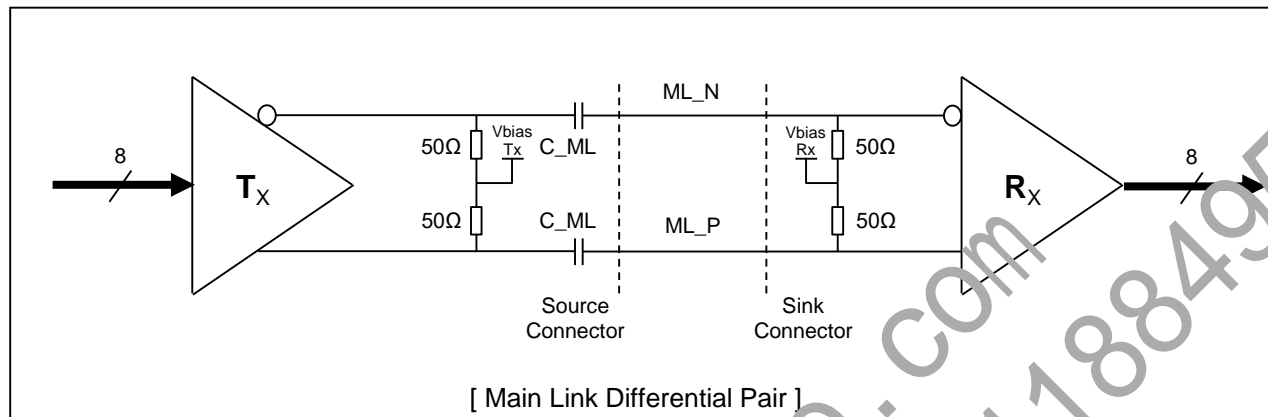
[eDP TP3_EQ EYE Mask Vertices]

Point	Time(UI)	Voltage(V)
1	Any UI location (0mV)	0.000
2	0.375<point2<0.625	0.035
3	Point1 + 0.45UI	0.000
4	0.375<point2<0.625	-0.035

[eDP RX_EQ EYE Mask Vertices]

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3-4-3. eDP Main Link Signal



Parameter	Symbol	Min	Typ	Max	Unit	Notes
Unit Interval for high bit rate (2.7Gbps / lane)	UI_HBR	-	370	-	ps	
Unit Interval for reduced bit rate (2.43Gbps / lane)	UI_2.16	-	412	-	ps	
Unit Interval for reduced bit rate (2.16Gbps / lane)	UI_2.16	-	461	-	ps	
Unit Interval for reduced bit rate (1.62Gbps / lane)	UI_HBR	-	617	-	ps	
Link Clock Down Spreading	Amplitude	0	-	0.5	%	
	Frequency	30	-	33	kHz	
Differential peak-to-peak Voltage at Sink side connector	$V_{TX-DIFFp-p}$	75	-	-	mV	TP3_EQ
EYE width at Sink side connector	$T_{TX-EYE-CONN}$	0.5	-	-	UI	TP3_EQ
Differential peak-to-peak voltage at RX package pin	$V_{RX-DIFFp-p}$	70	-	-	mV	TP4_EQ
EYE width at RX package pin	$T_{RX-EYE-CONN}$	0.45	-	-	UI	TP4_EQ
Rx DC common mode voltage	$V_{RX CM}$	0	-	1.0	V	
AC Coupling Capacitor	$C_{SOURCE-ML}$	75	-	200	nF	Source side

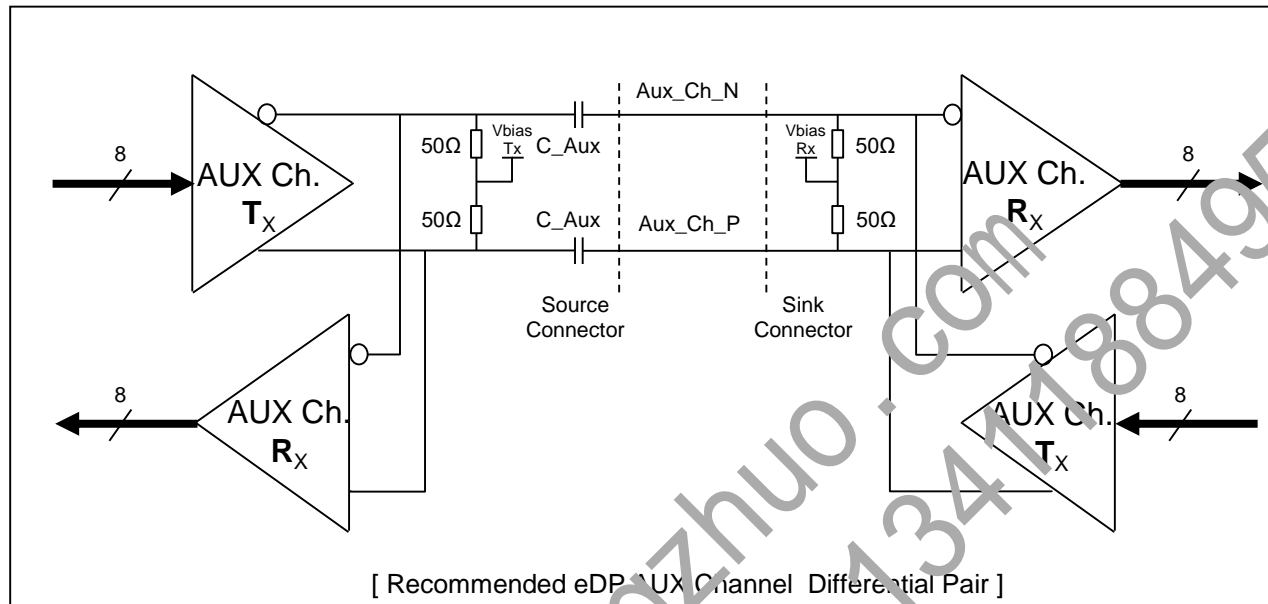
Note)

1. Termination resistor is typically integrated into the transmitter and receiver implementations.
2. AC Coupling Capacitor is not placed at the sink side.
3. In cabled embedded system, it is recommended the system designer ensure that EYE width and voltage are met at the sink side connector pins.



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3-4-4. eDP AUX Channel Signal



Parameter	Symbol	Min	Typ	Max	Unit	Notes
AUX Unit Interval	UI	0.4	-	0.6	us	
AUX Jitter at Tx IC Package Pins	Jitter	-	-	0.04	UI	Equal to 24ns
AUX Jitter at Rx IC Package Pins		-	-	0.05	UI	Equal to 30ns
AUX Peak-to-peak voltage at TX package pins (TP1)	$V_{AUX_DIFFp-p}$	0.18	0.20	1.38	V	
AUX Peak-to-peak voltage at TP3		0.14	-	1.36	V	
AUX EYE width at Connector Pins of Tx and Rx		0.98	-	-	UI	
AUX DC common mode voltage	V_{AUX-CM}	0	-	1.0	V	
AUX AC Coupling Capacitor	$C_{SOURCE-AUX}$	75		200	nF	Source side

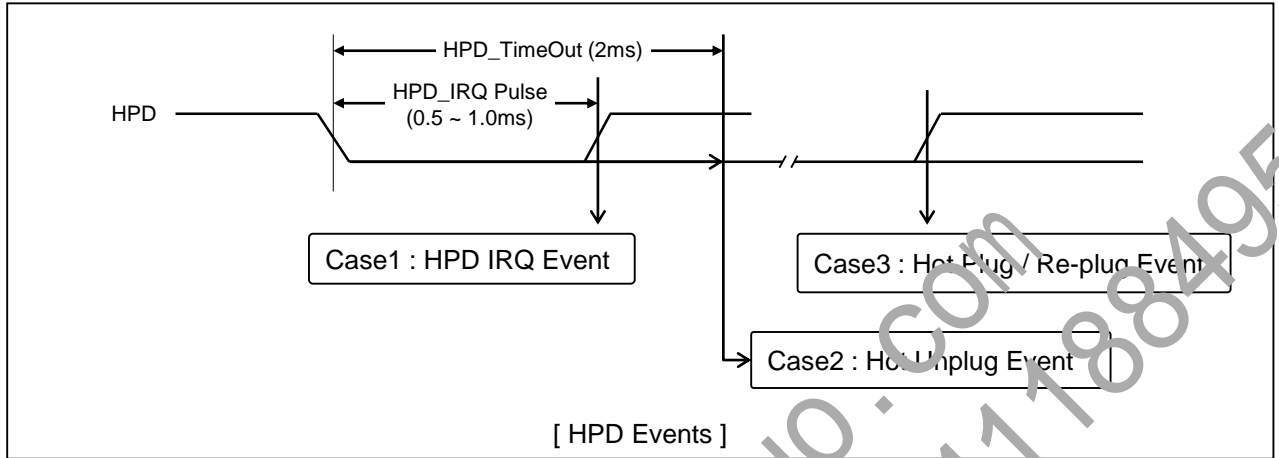
Note)

1. Termination resistor is typically integrated into the transmitter and receiver implementations.
2. AC Coupling Capacitor is not placed at the sink side.
3. $V_{AUX_DIFFp-p} = 2 * |V_{AUXP} - V_{AUXN}|$



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3-4-5. eDP HPD Signal



Parameter	Symbol	Min	Typ	Max	Unit	Notes
HPD Voltage	HPD	2.25	-	3.6	V	Sink side Driving
Hot Plug Detection Threshold		2.0	-	-	V	Source side Detecting
Hot Unplug Detection Threshold		-	-	0.8	V	
HPD_IRQ Pulse Width	HPD_IRQ	0.5	-	1.0	ms	
HPD_TimeOut		2.0	-	-	ms	HPD Unplug Event

Note)

1. HPD IRQ : Sink device wants to notify the Source device that Sink's status has changed so it toggles HPD line, forcing the Source device to read its Link / Sink Receiver DPCD field via the AUX-CH
2. HPD Unplug : The Sink device is no longer attached to the Source device and the Source device may then disable its Main Link as a power saving mode
3. Plug / Re-plug : The Sink device is now attached to the Source device, forcing the Source device to read its Receiver capabilities and Link / Sink status Receiver DPCD fields via the AUX-CH



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3-5. Signal Timing Specifications

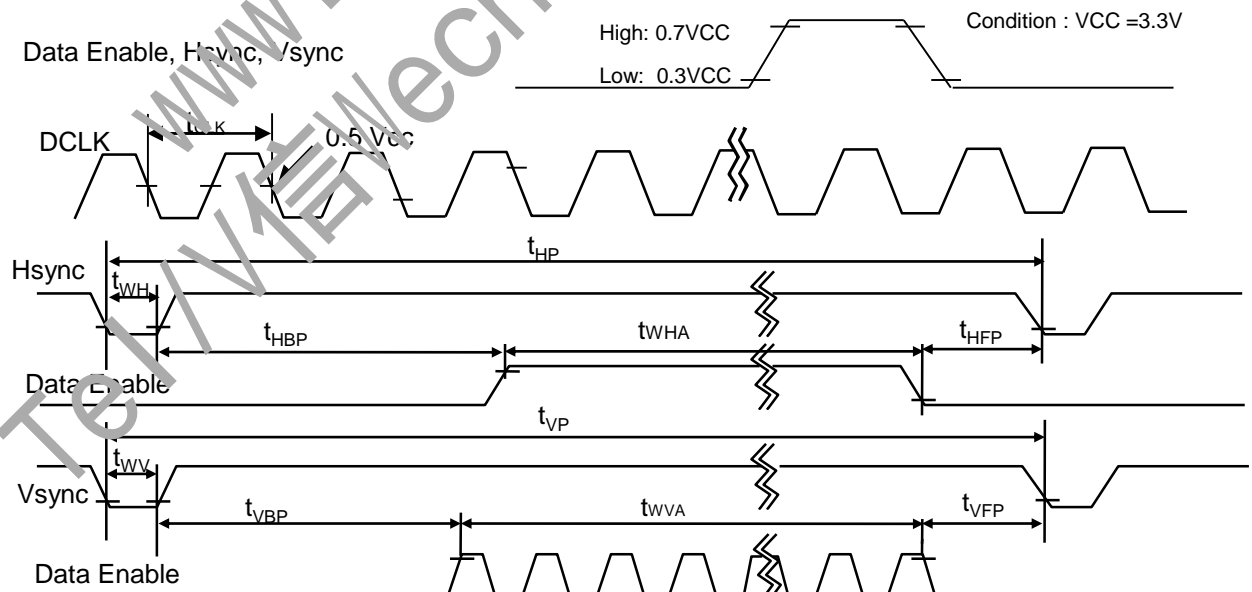
This is the signal timing required at the input of the User connector. All of the interface signal timing should be satisfied with the following specifications and specifications of eDP Tx/Rx for its proper operation.

Table 4. TIMING TABLE

ITEM	Symbol	Min	Typ	Max	Unit	Note
DCLK	Frequency	f_{CLK}	-	154.13	-	MHz
Hsync	Period	t_{HP}	-	2080	-	
	Width	t_{WH}	-	32	-	t_{CLK}
	Width-Active	t_{WHA}	1920			
Vsync	Period	t_{VP}	-	1235	-	
	Width	t_{WV}	-	6	-	t_{HP}
	Width-Active	t_{WVA}	1200			
Data Enable	Horizontal back porch	t_{HBP}	-	80	-	t_{CLK}
	Horizontal front porch	t_{HFP}	-	48	-	
	Vertical back porch	t_{VBP}	-	26	-	t_{HP}
	Vertical front porch	t_{VFP}	-	3	-	
Refresh rate		Hz	-	60	-	

Notice. all reliabilities are specified for timing specification based on refresh rate of 60Hz. However, LP140WU1 has a good actual performance even at lower refresh rate (e.g. 48Hz) for power saving Mode, whereas LP140WU1 is secured only for function under lower refresh rate. 60Hz at Normal mode, 48Hz at Power save mode. Don't care Flicker level (Power save mode).

3-6. Signal Timing Waveforms



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3-7. Color Input Data Reference

The brightness of each primary color (red, green and blue) is based on the 8-bit gray scale data input for the color ; the higher the binary input, the brighter the color. The table below provides a reference for color versus data input.

Table 6. COLOR DATA REFERENCE

Color		Input Color Data																							
		RED								GREEN								BLUE							
		MSB				LSB				MSB				LSB				MSB				LSB			
		R7	R6	R5	R4	R3	R2	R1	R0	G7	G6	G5	G4	G3	G2	G1	G0	B7	B6	B5	B4	B3	B2	B1	B0
Basic Color	Black	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Green	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
	Blue	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1
	Cyan	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
	Magenta	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1
	Yellow	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
	White	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
RED	RED (0)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	RED (1)	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
							
	RED (254)	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	RED (255)	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
GREEN	GREEN (0)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	GREEN (1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0
							
	GREEN (254)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0
	GREEN (255)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
BLUE	BLUE (0)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	BLUE (1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0
							
	BLUE (254)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0
	BLUE (255)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1

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3-8. Power Sequence

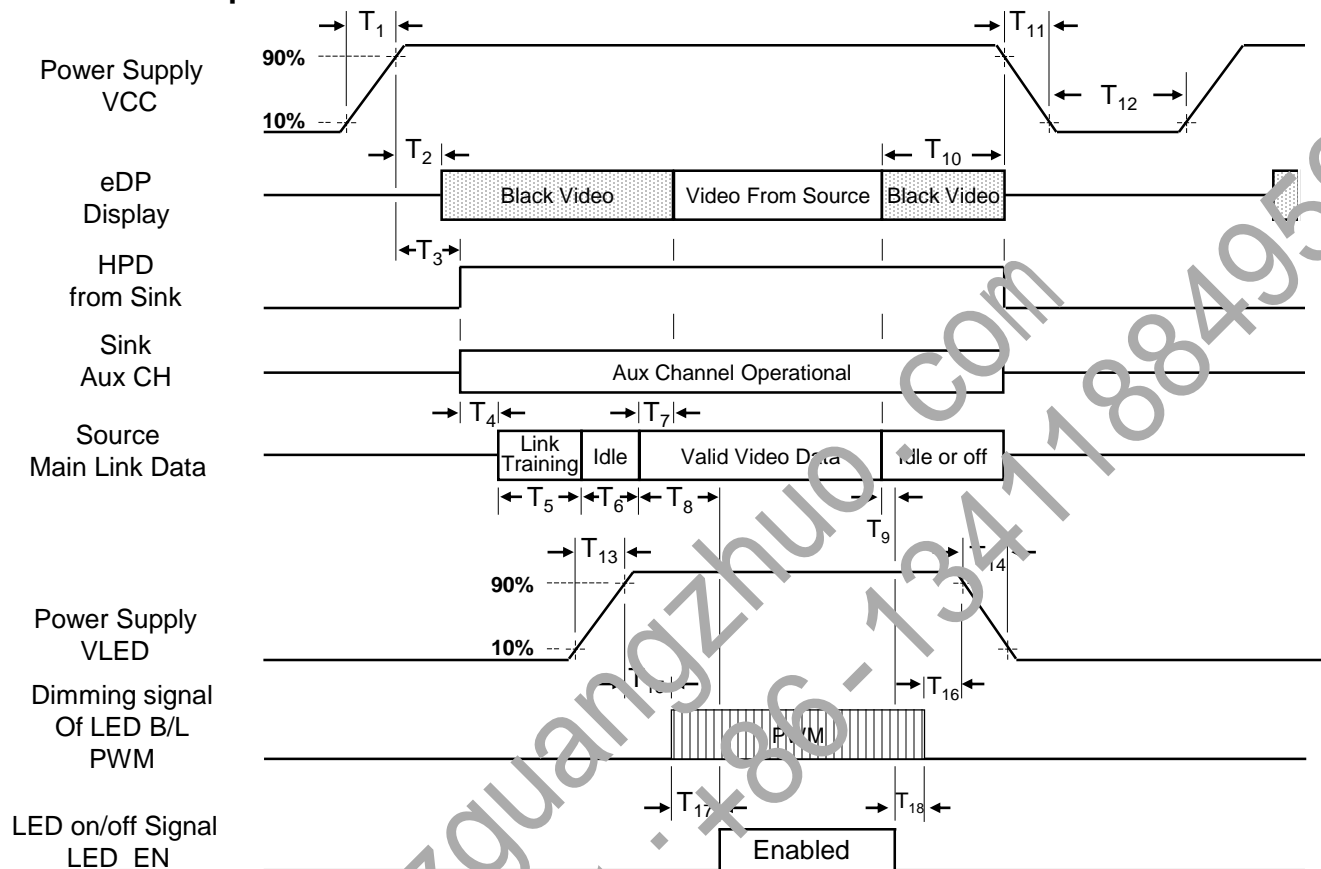


Table 6. POWER SEQUENCE TABLE

Symbol	Required By	Limits		Units	Notes	Symbol	Required By	Limits		Units	Notes
		Min	Max					Min	Max		
T ₁	Source	0.5	0	ms		T ₁₀	Source	35	500	ms	7
T ₂	Sink	0	80	ms	-	T ₁₁	Source	-	10	ms	-
T ₃	Sink	0	80	ms	-	T ₁₂	Source	500	-	ms	
T ₄	Source	-	-	ms	-	T ₁₃	Source	0.5	10	ms	-
T ₅	Source	-	-	ms	-	T ₁₄	Source	0.5	10	ms	-
T ₆	Source	-	-	ms	-	T ₁₅	Source	10	-	ms	-
T ₇	Sink	0	50	ms	-	T ₁₆	Source	10	-	ms	-
T ₈	Source	-	-	ms	5	T ₁₇	Source	0	-	ms	-
T ₉	Source	0	5	ms	6	T ₁₈	Source	0	-	ms	-

- Note:
- Do not insert the mating cable when system turn on.
 - Valid Data have to meet "3-3. eDP Signal Timing Specifications"
 - Video Signal, LED_EN and PWM need to be on pull-down condition on invalid status.
 - LGD recommend the rising sequence of VLED after the Vcc and valid status of Video Signal turn on.
 - Driving signal of B/L must be "On" after normal video signal (Normal operating data from source) input.
 - When VCC off, LGD suggests that LED EN to be dropped to low level within black video data for reddish prevention (T9 min:0ms / Max 5ms)
 - For stable operation of KSF BL, LGD suggests Black video data have to meet min 35ms

Product Specification

4. Optical Specification

Optical characteristics are determined after the unit has been ‘ON’ and stable for approximately 20 minutes in a dark environment at 25°C. The values specified are at an approximate distance 50cm from the LCD surface at a viewing angle of Φ and Θ equal to 0°.

FIG. 1 presents additional information concerning the measurement equipment and method.

FIG. 1 Optical Characteristic Measurement Equipment and Method

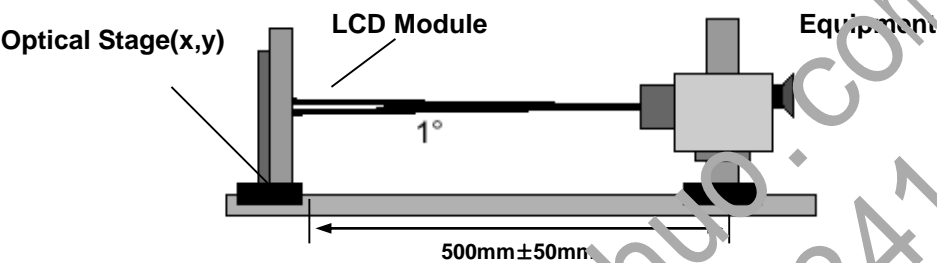


Table 7. OPTICAL CHARACTERISTICS

Ta=25°C, VCC=3.3V, fv=60Hz

Parameter		Symbol	Values			Units	Notes
			Min	Typ	Max		
Contrast Ratio		CR	1000	1200	-		1
Surface Luminance, white		L _w (H)	340	400	-	cd/m ²	2
Luminance Variation		Δ WHITE (5P)	-	-	20	%	3
		Δ WHITE (13P)	-	-	35		
Response Time (Ta=30°C)		Tr + Tf	-	25	35	ms	4
Color Gamut		sRGB	95%	100%	-		CIE 1931
Color Coordinates	RED	R _x	Typical - 0.03	0.656	Typical + 0.03		5
		R _y		0.329			
	GREEN	G _x		0.297			
		G _y		0.602			
	BLUE	B _x		0.147			
		B _y		0.064			
	WHITE	W _x		0.313			
		W _y		0.329			
Viewing Angle	x axis, right (Φ=0°)	Θ _r	80	85	-	Degree	6
	x axis, left (Φ=180°)	Θ _l	80	85	-		
	y axis, up (Φ=90°)	Θ _u	80	85	-		
	y axis, down (Φ=270°)	Θ _d	80	85	-		
Gray Scale			1.7	2.2	2.7		7

Product Specification

- Note)
1. It should be measured in the center of screen(1 Point). Contrast Ratio(CR) is defined mathematically as

$$\text{Contrast Ratio(1 Point)} = \frac{\text{Surface Luminance with all white pixels}}{\text{Surface Luminance with all black pixels}}$$
 2. Surface luminance is the average of 5 point across the LCD surface 50cm from the surface with all pixels displaying white. For more information see FIG 2.

$$L_{WH} = \text{Average}(55,33,37,73,77\text{Point})$$
 3. The variation in surface luminance , The panel total variation (δ WHITE) is determined by measuring N at each test position 1 through 13 and then defined as following numerical formula.
For more information see FIG 2.

$$\delta \text{ WHITE (5P)} = \left(1 - \frac{\text{Min}(33,37,55,73,77 \text{ Point})}{\text{Max}(33,37,55,73,77 \text{ Point})} \right) \times 100$$

$$\delta \text{ WHITE (13P)} = \left(1 - \frac{\text{Min (All measuring Point)}}{\text{Max (All measuring Point)}} \right) \times 100$$
 4. Response time is the time required for the display to transition from Black to White.
For additional information see FIG 3.
 5. It should be measured in the center of screen (1Point).
Color coordinates must be measured with the equipment which has optical wavelength resolution of under 2nm. (ex. PR-670, PR-680, CS-2000/2000A ...)
 6. Viewing angle is the angle at which the contrast ratio is greater than 10. The angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface. For more information see FIG 4.
 7. Gray scale specification

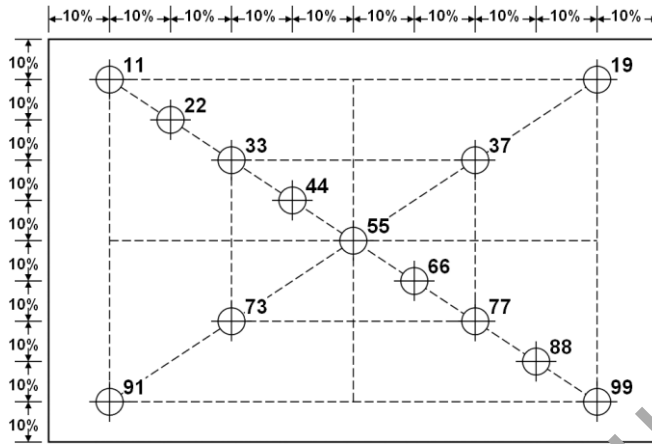
Gray Level	Luminance [%] (Typ)
L0	TBD
L31	TBD
L63	TBD
L95	TBD
L127	TBD
L159	TBD
L191	TBD
L223	TBD
L255	100



Product Specification

FIG. 2 Luminance

<Measuring point for Average Luminance & measuring point for Luminance variation>



H,V : ACTIVE AREA

5 Point : 33, 55, 77, 37, 73

13 Point : 11~99 Point all

FIG. 3 Response Time

The response time is defined as the following figure and shall be measured by switching the input signal for "black" and "white".

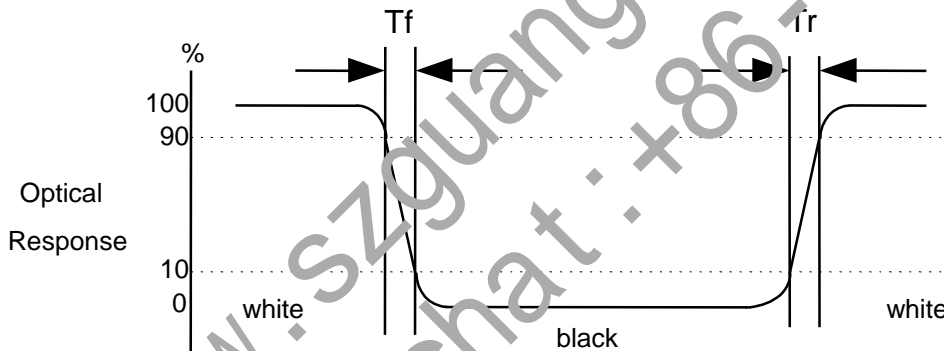
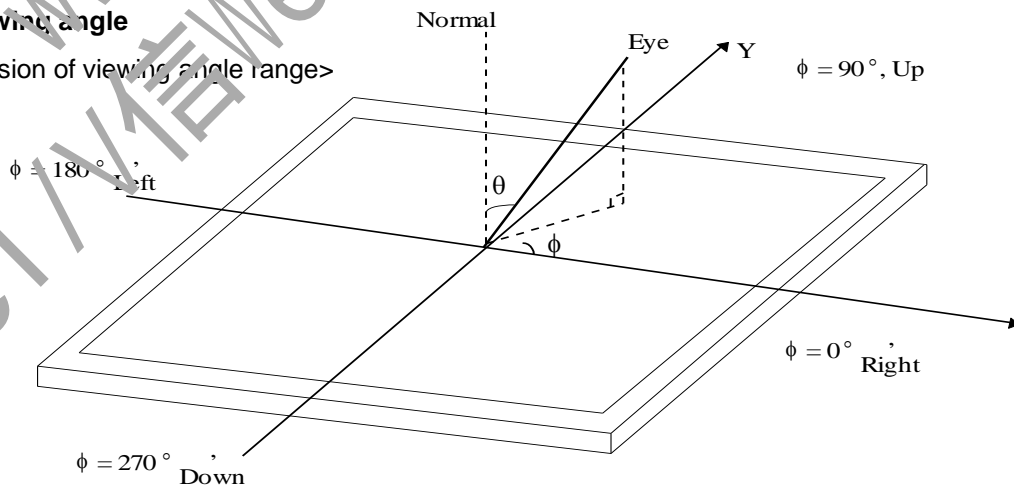


FIG. 4 Viewing angle

<Dimension of viewing angle range>



Product Specification

5. Mechanical Characteristics

The contents provide general mechanical characteristics for the model LP140WU1. In addition the figures in the next page are detailed mechanical drawing of the LCD.

Outline Dimension	Horizontal	306.59 ± 0.3 mm
	Vertical	198.40 ± 0.5 mm
	Thickness	1.80 ± 0.15 mm (W/C PCBA) 3.95 mm (W PCBA, Max.) 2.40/3.95 mm (User CNT, Min./Max.)
Upper Polarizer Dimension	Horizontal	303.99 ± 0.3 mm
	Vertical	190.90 ± 0.3 mm
Active Display Area	Horizontal	301.59 ± 0.15 mm
	Vertical	188.50 ± 0.15 mm
Weight	170g (Max.)	
Surface Treatment	Anti glare treatment of the front polarizer (3H)	

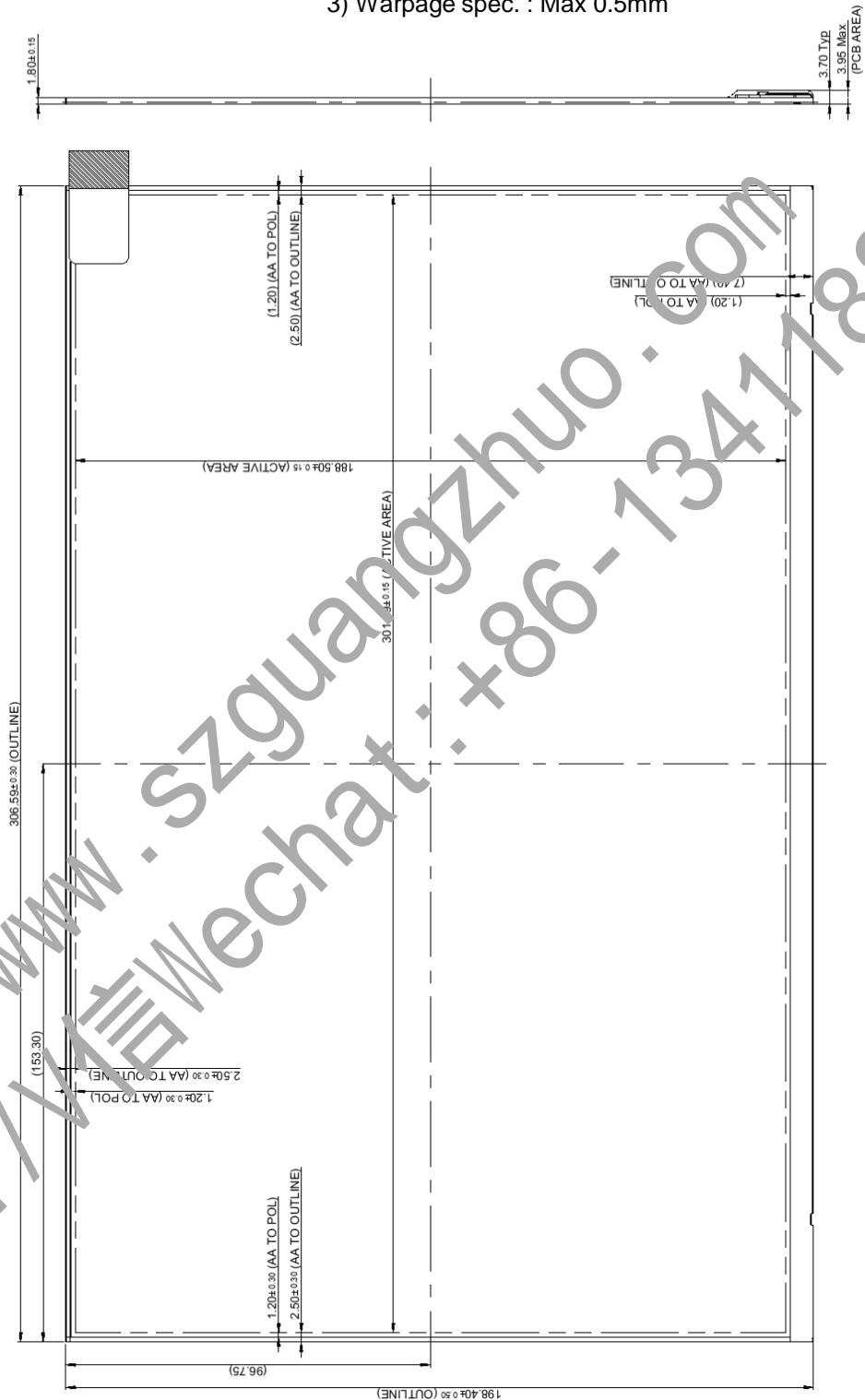


Product Specification

<FRONT VIEW>

Notes (Measurement method refer to the Appendix C)

- 1) Unit[mm], General tolerance : $\pm 0.5\text{mm}$
- 2) All components of LCM is under upper POL.
- 3) Warpage spec. : Max 0.5mm

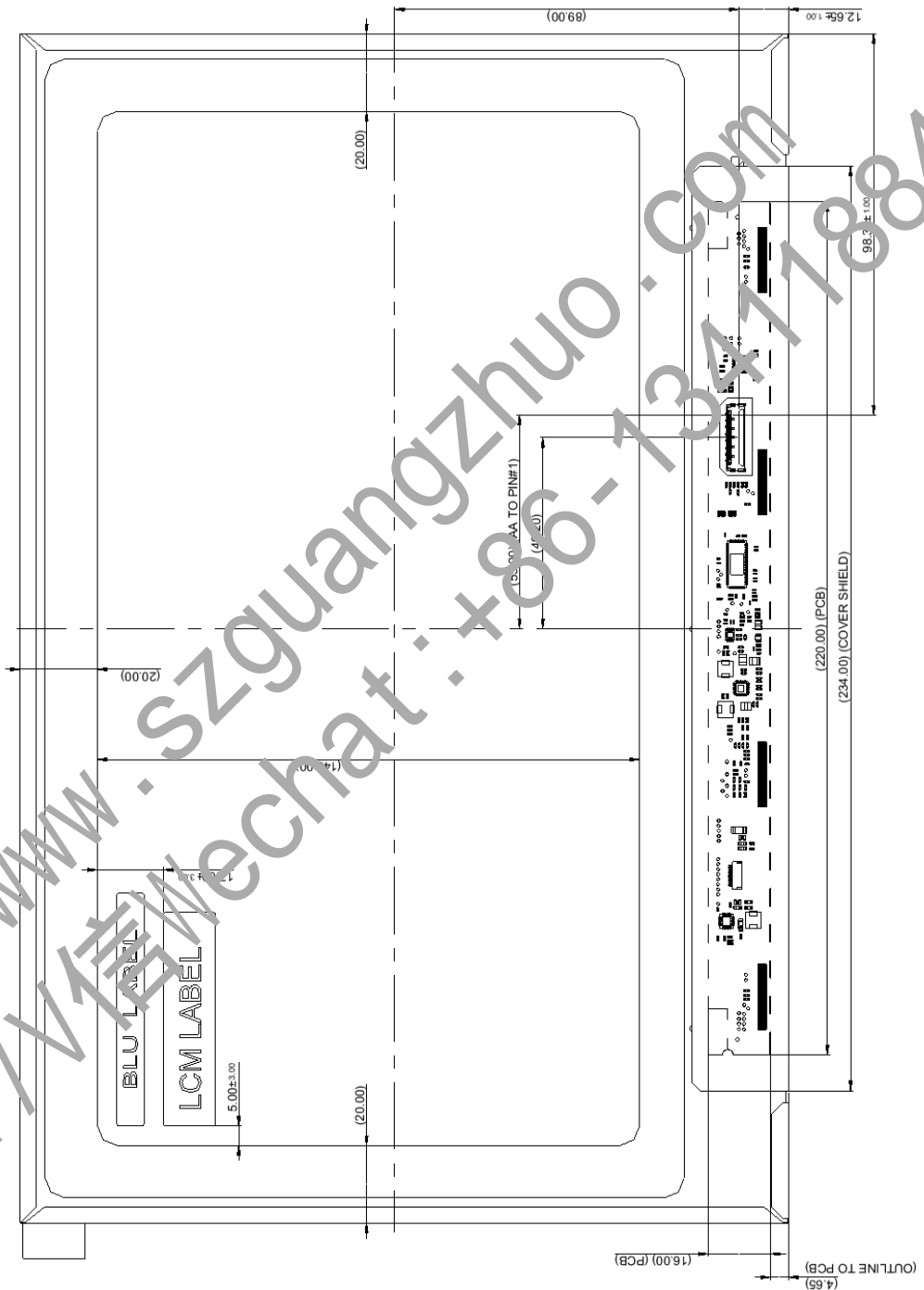




Product Specification

<REAR VIEW>

Note) Unit:[mm], General tolerance: $\pm 0.5\text{mm}$
LCM Label Information refer to the page 26



Product Specification

6. Reliability

Environment test condition

No.	Test Item	Conditions
1	High temperature storage test	Ta= 60°C, 240h
2	Low temperature storage test	Ta= -20°C, 240h
3	High temperature operation test	Ta= 50°C, 50%RH, 240h
4	Low temperature operation test	Ta= 0°C, 240h
5	Vibration test (non-operating)	Random, 1.0Grms, 10 ~ 300Hz(PSD 0.0025) 3 axis, 30min/axis
6	Shock test (non-operating)	- No functional or cosmetic defects following a shock to all 6 sides delivering at least 180 G in a half sine pulse no longer than 2 ms to the display module - No functional defects following a shock delivering at least 200 g in a half sine pulse no longer than 2 ms to each of 6 sides. Each of the 6 sides will be shock tested with one each display, for a total of 6 displays
7	Altitude	operating 0 ~ 10,000 feet (3,048m) 24Hr storage / shipment 0 ~ 40,000 feet (12,192m) 24Hr
8	ESD	± 8kV for contact discharge ± 15kV for air discharge

[Result Evaluation Criteria]

1. Comparing the initial functional FOS status, there should be no major change which might affect the practical display function when the display reliability test is conducted.
2. After conduct reliability tests, LGD guarantees only functional FOS quality.
3. In the Reliability Test, Confirm performance after leaving in room temp.
4. In the standard condition, there shall be no practical problems that may affect the display function 24 hours later after reliability test. After the reliability test, we can guarantee the product only when the corrosion is causing its malfunction. The corrosion causing no functional defect can not be guaranteed.

※ Remark: MTBF (Excluding the LED) 50,000 hours with a confidence level 90%
 (Based on 60°C, 1,000 hours Reliability Test with 10pcs LCM)



Product Specification

7. International Standards

7-1. Safety

- a) IEC 62368-1, The International Electro-technical Commission(IEC).
Audio/video, Information and Communication Technology Equipment - Safety Requirements.
- b) EN IEC 62368-1, European Committee for Electro-technical Standardization (CENELEC)
Audio/video, Information and Communication Technology Equipment - Safety Requirements
- c) UL 62368-1, UL LLC.
Audio/video, Information and Communication Technology Equipment - Safety Requirements
- d) CAN/CSA C22.2 No.62368-1, Canadian Standards Association (CSA).
Audio/video, Information and Communication Technology Equipment - Safety Requirements
- e) IEC 60950-1, The International Electro technical Commission (IEC).
Information Technology Equipment - Safety - Part 1 : General Requirements

7-2. Environment

- a) RoHS, Commission Delegated Directive (EU) 2015/863 of 31 March 2015 amending Annex II to Directive 2011/65/EU of the European Parliament and of the Council

Product Specification

8. Packing

8-1. Designation of Lot Mark

[DETAIL INFORMATION OF PPID LABEL AND REVISION CODE]



1) MFG ID :

It is subject to change with BLU assembly company.
Please refer to the below table for detail.

BLU assembly company	MFG ID
NJ Heesung	HMNLG
NJ Starion	ZSNLG
King Display	KLRLG

2) PPID Label Revision :

It is subject to change with Dell event. Please refer to the below table for detail.

Classification	No Change	1st Revision	2nd Revision	...	9th Revision	...
SST(WS)	X00	X01	X02	...	X09	...
PT(ES)	X10	X11	X12	...	X19	...
ST(CS)	X20	X21	X22	...	X29	...
XB(MP)	A00	A01	A02	...	A09	...

Country of Origin	Factory ID
CU: China	LGDNJ
KR: Korea	-

Product Specification

a) Lot Mark

A	B	C	D	E	F	G	H	I	J	K	L	M
---	---	---	---	---	---	---	---	---	---	---	---	---

A,B,C : SIZE(INCH)
 E : MONTH

D : YEAR
 F ~ M : SERIAL NO.

Note

1. YEAR

Year	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Mark	K	L	M	N	P	R	S	T	U	V

2. MONTH

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Mark	1	2	3	4	5	6	7	8	9	A	B	C

b) Location of Lot Mark

Serial No. is printed on the label. The label is attached to the backside of the LCD module.
 This is subject to change without prior notice.

8-2. Packing Form

a) Package quantity in one box : 20pcs

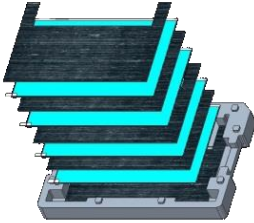
b) Box Size : 410 x 273 x 244



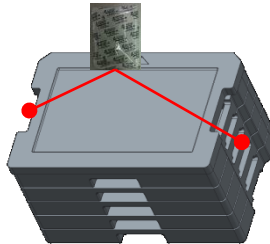
Product Specification

8-3. Packing Assembly

① put a cushion on the Tray
and Load LCM and cushion alternately



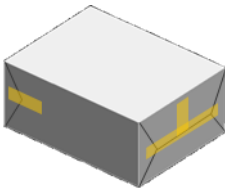
② 5Tray stack + Cover Tray
+ Desiccant 2ea



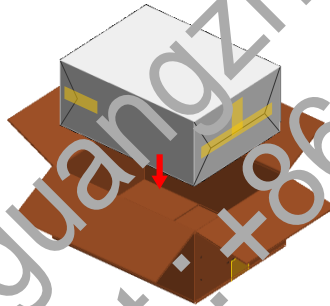
③ Pack the piled Tray by the AL Bag



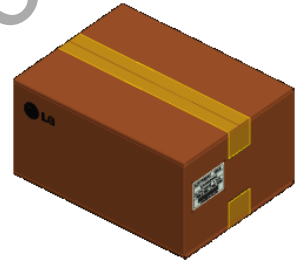
④ Taping AL Bag



⑤ Tray assy + AL Bag put in the box



⑥ Taping Box

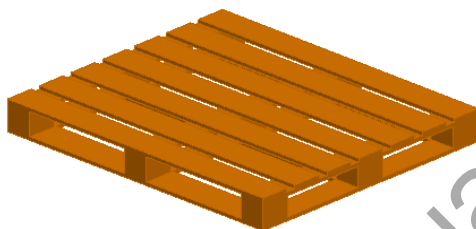


NO.	DESCRIPTION	MATERIAL
1	LCD Module	
2	BAG	AL
3	TAPE	MASKING 20MMX50M
4	PACKING, Tray	EP0
5	Desiccant	Power Dry
6	BOX	SW Paper
7	TAPE	OPP 70MMX300M
8	LABEL	ART 100X70

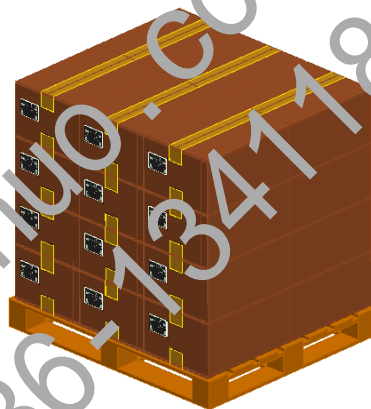
Product Specification

8-3. Packing Assembly (Pallet)

1. Pallet Ready



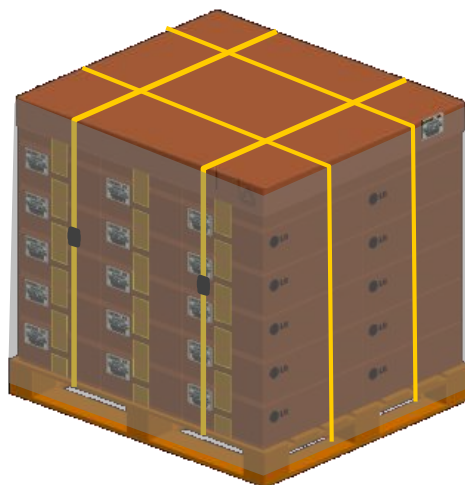
2. 4 x 2 x 4 Box Pattern



3. Angle Cover & Wrapping



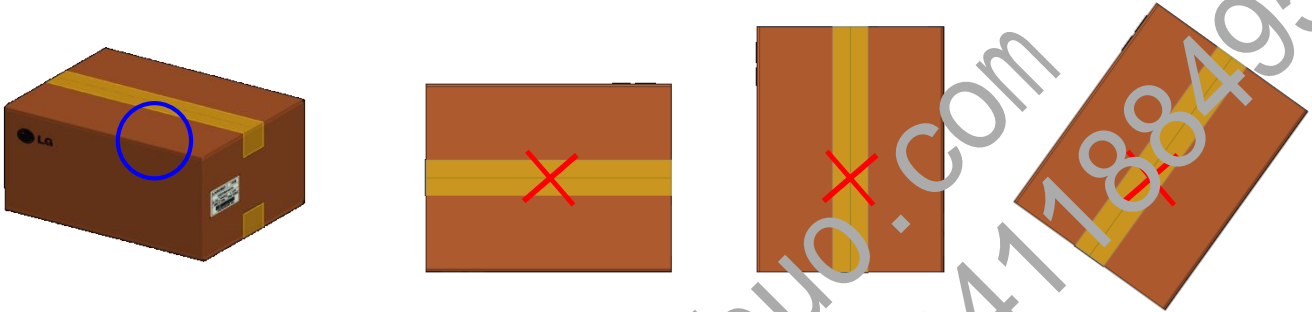
4. Banding



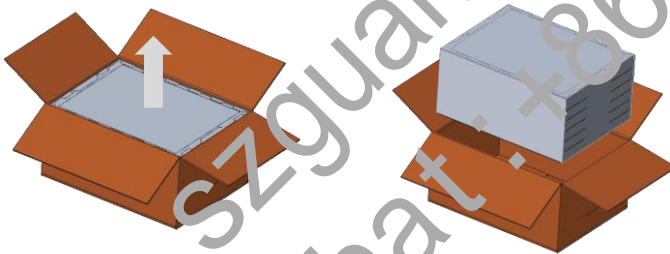


8-4. Precautions for unpacking the Box

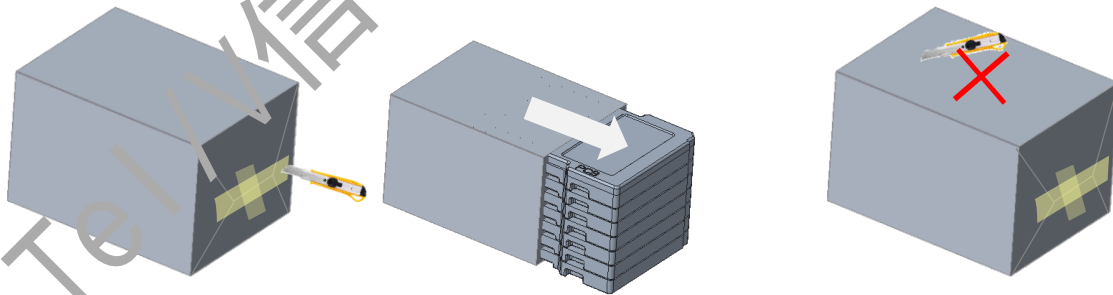
a.) Don't throw or tilt the box and put it on a flat surface.



b.) Place the box on a flat floor and Take out the AL bag vertically.



c.) Cut the tape on the side of the bag with a knife and Take out the tray horizontally.



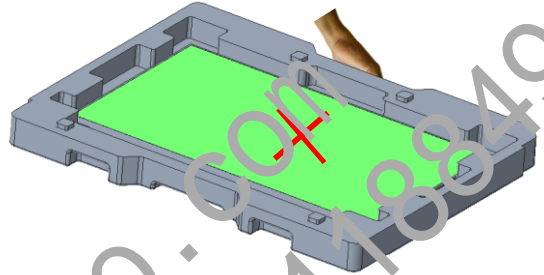
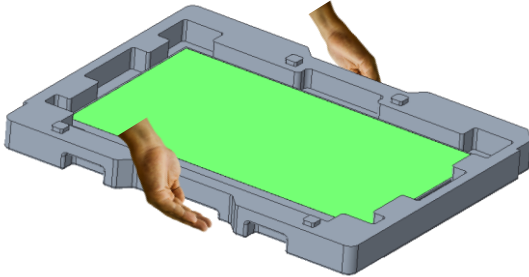
**Caution : Do not cut the top of the bag with a knife.
(The Knife can damage product)**



Product Specification

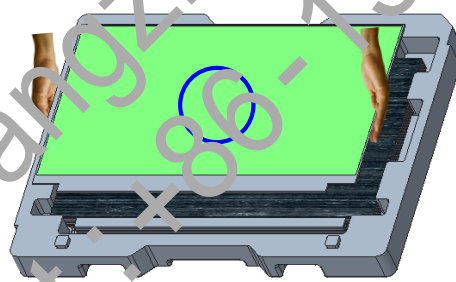
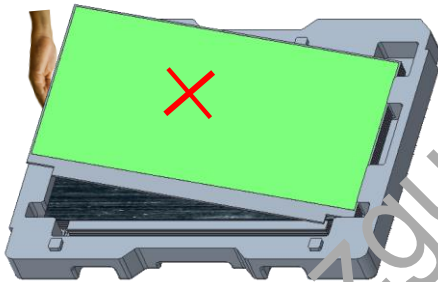
8-5. Precautions for Handling tray

- a.) Hold center of short or long side of the tray with both hands when handling one or more trays.

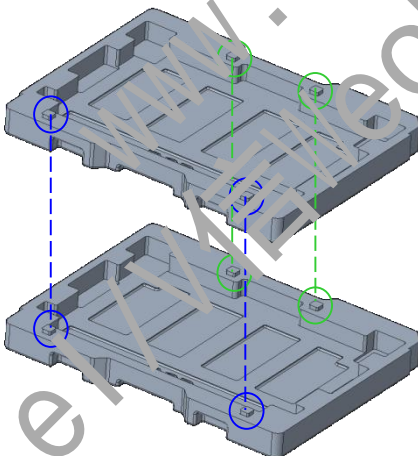


Caution : Do not handle with only one hand.

- b.) Always place tray on flat surface and Don't tilt with one hand to take out.



- c.) When stacking trays, Please align same position of the protrusion of each tray.



If not Aligned,
The tray may slip without being loaded.

- d.) The maximum stacking quantity is equal to the number of loads per box.
- Recommended as above because heavier weight can cause muscular skeletal disease and operator handling errors.



Product Specification

9. PRECAUTIONS

Please pay attention to the followings when you use this TFT LCD module.

9-1. MOUNTING PRECAUTIONS

- (1) You must mount a module using holes arranged in four corners or four sides.
- (2) You should consider the mounting structure so that uneven force (ex. Twisted stress) is not applied to the module. And the case on which a module is mounted should have sufficient strength so that external force is not transmitted directly to the module.
- (3) Please attach the surface transparent protective plate to the surface in order to protect the polarizer. Transparent protective plate should have sufficient strength in order to resist external force.
- (4) You should adopt radiation structure to satisfy the temperature specification.
- (5) Acetic acid type and chlorine type materials for the cover case are not desirable because the former generates corrosive gas of attacking the polarizer at high temperature and the latter causes circuit break by electro-chemical reaction.
- (6) Do not touch, push or rub the exposed polarizers with glass, tweezers or anything harder than HB pencil lead. And please do not rub with dust clothes with chemical treatment. Do not touch the surface of polarizer for bare hand or greasy cloth. (Some cosmetics are detrimental to the polarizer.)
- (7) When the surface becomes dusty, please wipe gently with absorbent cotton or other soft materials like chamois soaks with petroleum benzen. Normal-hexane is recommended for cleaning the adhesives used to attach front / rear polarizers. Do not use acetone, toluene and alcohol because they cause chemical damage to the polarizer.
- (8) Wipe off saliva or water drops as soon as possible. Their long time contact with polarizer causes deformations and color fading.
- (9) Do not open the case because inside circuits do not have sufficient strength.

9-2. OPERATING PRECAUTIONS

- (1) The spike noise causes the mis-operation of circuits. It should be lower than following voltage :
 $V = \pm 200mV$ (Over and under shock voltage)
- (2) Response time depends on the temperature. (In lower temperature, it becomes longer.)
- (3) Brightness depends on the temperature. (In lower temperature, it becomes lower.)
And in lower temperature, response time (required time that brightness is stable after turned on) becomes longer.
- (4) Be careful for condensation at sudden temperature change. Condensation makes damage to polarizer or electrical contacted parts. And after fading condensation, smear or spot will occur.
- (5) When fixed patterns are displayed for a long time, remnant image is likely to occur.
- (6) Module has high frequency circuits. Sufficient suppression to the electromagnetic interference shall be done by system manufacturers. Grounding and shielding methods may be important to minimized the interference.



Product Specification

9-3. ELECTROSTATIC DISCHARGE CONTROL

Since a module is composed of electronic circuits, it is not strong to electrostatic discharge. Make certain that treatment persons are connected to ground through wrist band etc. And don't touch interface pin directly.

9-4. PRECAUTIONS FOR STRONG LIGHT EXPOSURE

Strong light exposure causes degradation of polarizer and color filter.

9-5. STORAGE

When storing modules as spares for a long time, the following precautions are necessary.

- (1) Store them in a dark place. Do not expose the module to sun light or fluorescent light. Keep the temperature between 5°C and 35°C at normal humidity.
- (2) The polarizer surface should not come in contact with any other object.
It is recommended that they be stored in the container in which they were shipped.

9-6. HANDLING PRECAUTIONS FOR PROTECTION FILM

- (1) When the protection film is peeled off, static electricity is generated between the film and polarizer. This should be peeled off slowly and carefully by people who are electrically grounded and with well ion-blown equipment or in such a condition, etc.
- (2) The protection film is attached to the polarizer with a small amount of glue. If some stress is applied to rub the protection film against the polarizer during the time you peel off the film, the glue is apt to remain on the polarizer.
Please carefully peel off the protection film without rubbing it against the polarizer.
- (3) When the module with protection film attached is stored for a long time, sometimes there remains a very small amount of glue still on the polarizer after the protection film is peeled off.
- (4) You can remove the glue easily. When the glue remains on the polarizer surface or its vestige is recognized, please wipe them off with absorbent cotton waste or other soft material like chamois soaked with normal-hexane.

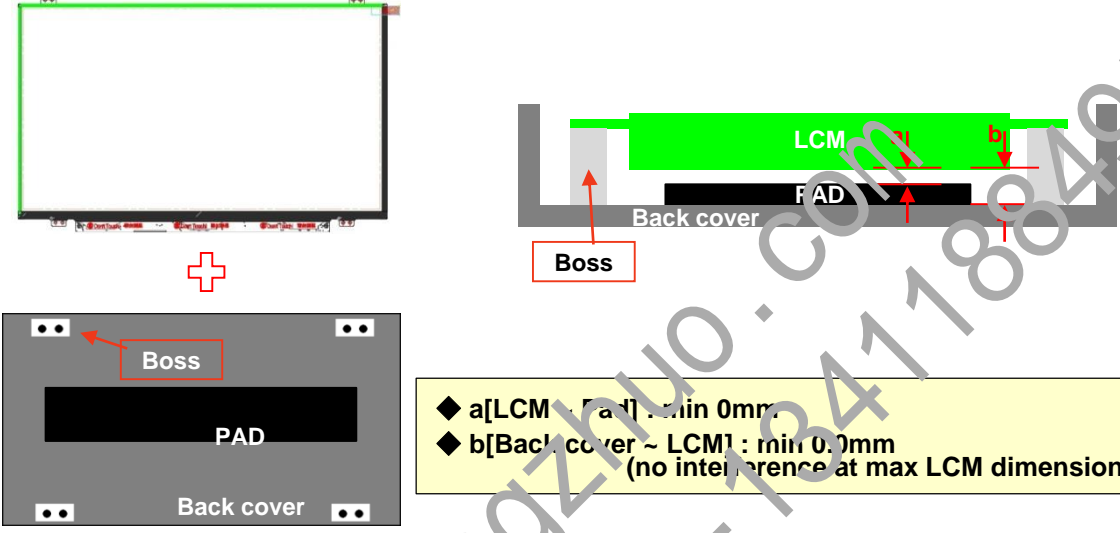
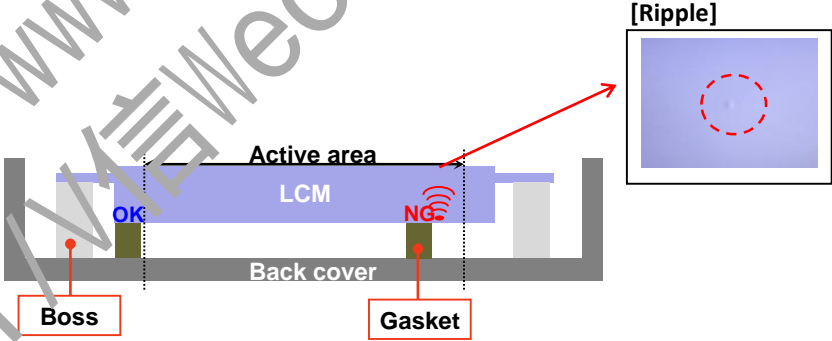
9-7. THE LGD QA RESPONSIBILITY WILL BE AVOIDED IN CASE OF BELOW

- (1) When the customer attaches TSM(Touch Sensor Module) on LCM without Supplier's approval.
- (2) When the customer attaches cover glass on LCM without Supplier's approval.
- (3) When the LCMs were repaired by 3rd party without Supplier's approval.
- (4) When the LCMs were treated like Disassemble and Rework by the Customer and/or Customer's representative without supplier's approval.



Product Specification

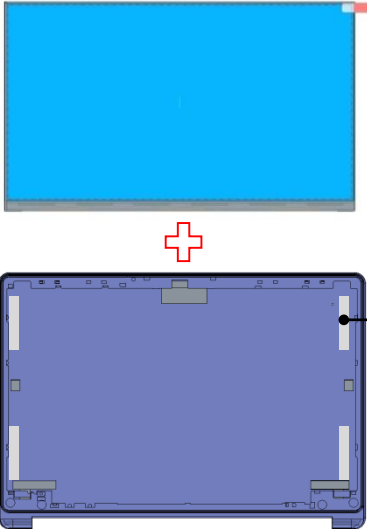
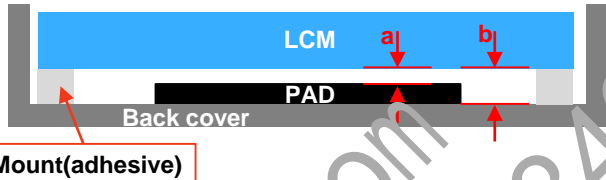
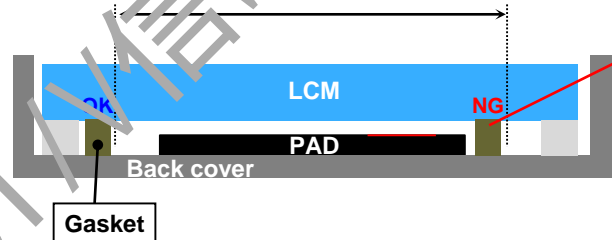
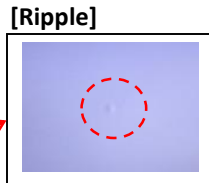
Appendix A. LGD Proposal for system cover design.

1	Gap check for securing the enough gap between LCM and System back cover.
	 <p> ◆ a[LCM ~ FAD] : min 0mm ◆ b[Back cover ~ LCM] : min 0.0mm (no interference at max LCM dimension) </p>
Risk point	Rear side of LCM is sensitive against external stress, and previous check about interference is highly needed.
Suggestion	In case there is something from system cover comes into the boundary above, mechanical interference may cause the FOS defects. (ex: Ripple, White spot..)
2	Gasket position
	
Risk point	Ripple or white spot can be happened by interference between pad and LCM when gap is not enough.
Suggestion	It is recommended that gasket is posited out of active area .



Product Specification

Appendix A. LGD Proposal for system cover design.

3	Gap check for securing the enough gap between LCM and System back cover.
	 <div data-bbox="639 741 1350 861" style="border: 1px solid black; padding: 5px;"> <p>◆ a[LCM ~ Pad] : min 0mm</p> <p>◆ b[Back cover ~ LCM] : min 0.0mm (no interference at max LCM dimension)</p> </div>
Risk point	Rear side of LCM is sensitive against external stress, and previous check about interference is highly needed.
Suggestion	In case there is something from system cover comes into the boundary above, mechanical interference may cause the FOS defects. (ex: Ripple, White spot..)
4	Gasket position
	
Risk point	Ripple or white spot can be happened by interference between pad and LCM when gap is not enough.
Suggestion	It is recommended that gasket is posited out of active area .



Product Specification

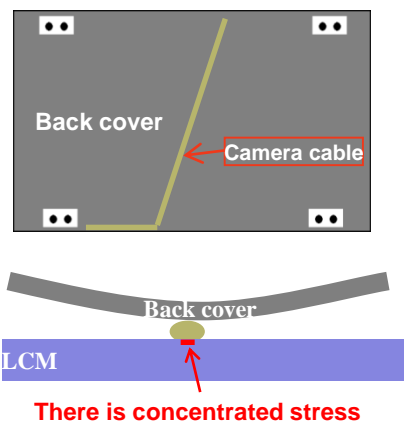
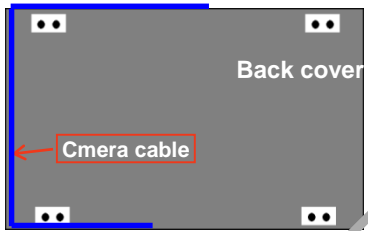


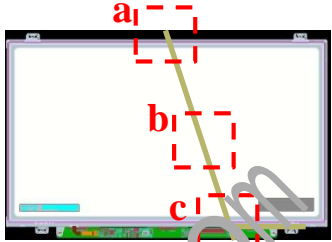
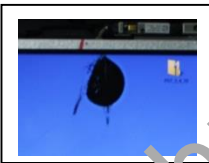

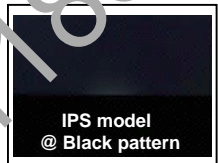
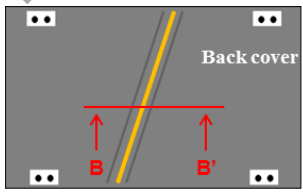
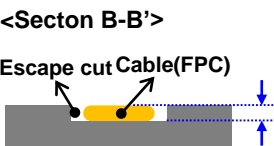
Appendix A. LGD Proposal for system cover design.

5	Check the gap between front cover and LCM(glass)
	<div data-bbox="92 367 649 550"> <p>Diagram showing the gap 'a' between the front cover and the LCM on the back cover. The gap is indicated by a red arrow and labeled 'a'.</p> </div> <div data-bbox="706 367 1306 637"> <p>Diagram showing the liquid crystal area and the protrusion or pad on the front cover. The liquid crystal area is labeled 'Liquid crystal area' and the protrusion is labeled 'Protrusion or pad'.</p> </div> <div data-bbox="1135 656 1349 840"> <p>Diagram showing the safety area and the seal on the front cover. The safety area is labeled 'Safety area' and the seal is labeled 'SEAL'.</p> </div> <div data-bbox="107 724 921 859"> <p>[OK] $0.1\text{mm} \leq a \leq 0.3\text{mm}$ [Caution] $0.0\text{mm} \leq a < 0.1\text{mm}$, $0.3\text{mm} < a \leq 0.5\text{mm}$ [NG] $a \leq 0\text{mm}$ (overlap), $a > 0.5\text{mm}$ (leakage)</p> </div>
Risk point	Ripple can be happened by little gap between glass and front cover.
Suggestion	<p>Keep the gap between front cover and LCM from 0.1 to 0.3mm</p> <p>Ripple is prevented by add protrusion shape at the back side of front cover. In this case, protrusion must be created outside of liquid crystal area</p>



Product Specification

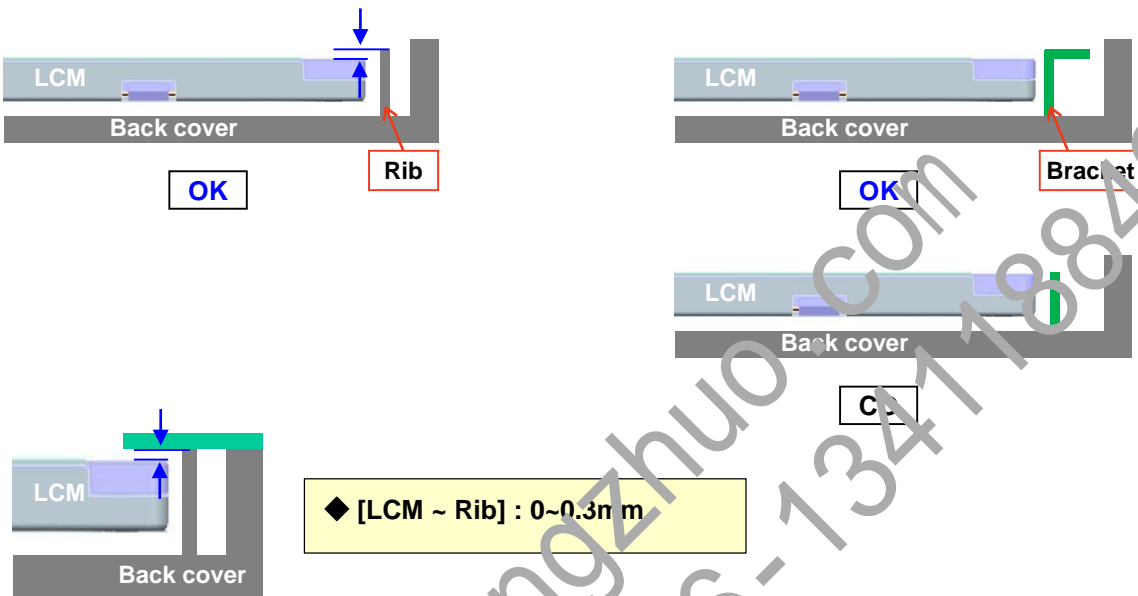
Appendix A. LGD Proposal for system cover design.

6	Checking the path of the System cables
 <p>[Suggestion]</p>  <p>[Cable path]</p>  <p>[Add pad]</p> 	 <p>[Panel crack at "a"]</p>  <p>[White spot at "b"]</p>  <p>[Light leakage at "c"]</p>  <p>[Add cut]</p>  <p><Section B-B'></p>  <p>Escape cut depth = Cable thickness</p>
<p>Risk point</p>	<p>LCM is easily damage by camera cable when cable is protruded from back cover.</p> <p>It is caused panel crack or white spot by concentrated stress and light leakage by panel bending at IPS model.</p> <p>It is recommended that camera cable path put outside of LCM.</p> <p>It is recommended that pad is added at both side of cable.</p> <p>Suggestion</p> <p>If cable path must be cross middle area of system, @slim & narrow bezel</p> <ol style="list-style-type: none"> 1) Cable type is recommended to use flexible (Use FPC type). 2) Add escape cut on back cover and add round at the edge of cut <p>Depth of escape cut recommended to set the same as FPC thickness.</p>



Product Specification

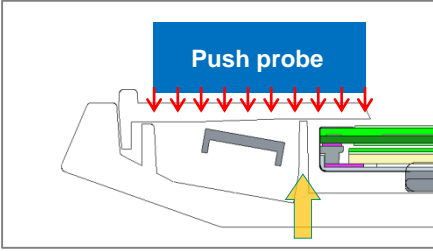
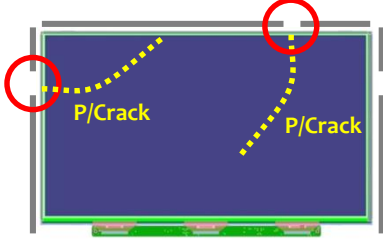
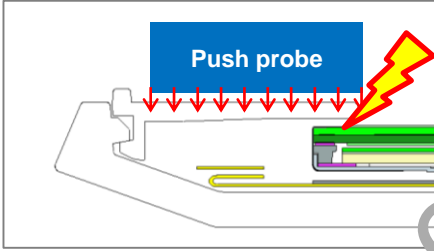
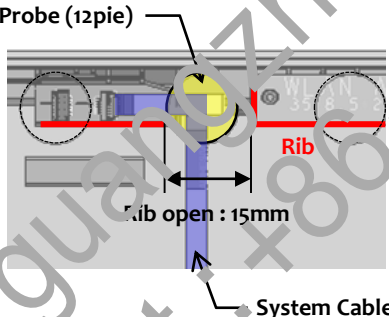
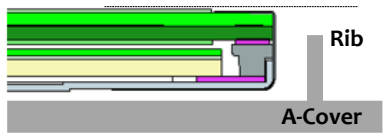
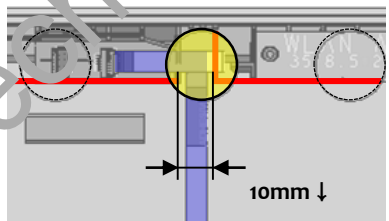
Appendix A. LGD Proposal for system cover design.

7	Check the rib or Bracket on back cover
 <p>◆ [LCM ~ Rib] : 0~0.3mm</p>	
Risk point	It is necessary that the height of back cover rib or bracket is higher than LCM height. It can prevent direct compression of panel at LCM edge.
Suggestion	"┐" shape bracket is stronger than "I" shape one. It is recommended that rib height is same or more with LCM height. In this case it must be considered light leakage at front cover, too.



Product Specification

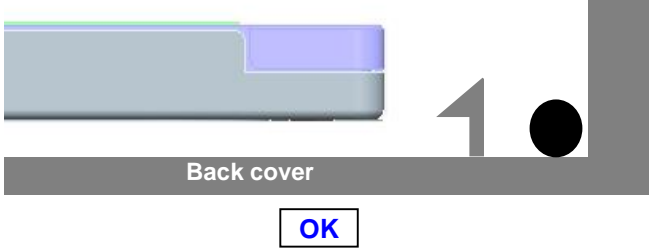
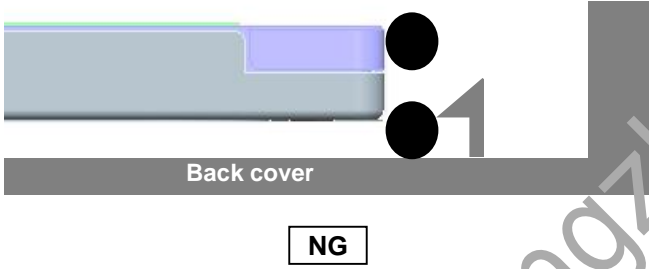
Appendix A. LGD Proposal for system cover design.

8	Rib design for panel crack prevention
<p>Rib 有</p>  <p>Rib structure supported by load LCM applied load distribution</p> <p>[Suggestion]</p>  <p>P/Crack</p> <p>P/Crack</p> <p>Continuous Rib design</p>	<p>Rib 無</p>  <p>Push probe</p> <p>Direct load is transferred to LCM It is vulnerable to panel crack.</p>  <p>Probe (12pie)</p> <p>Rib</p> <p>Rib open : 15mm</p> <p>System Cable</p>  <p>Rib</p> <p>A-Cover</p>  <p>10mm ↓</p>
<p>Risk point</p> <p>Suggestion</p>	<p>When the area without the A-Cover Rib and the push point are matched, It is concentrated and vulnerable to panel cracks..</p> <p>LCM Peripheral Rib should be long enough without discontinuity.</p> <p>In case of unavoidable Rib discontinuity, Rib open interval is set to 10pie or less.</p> <p>Rib should be higher than LCM upper pol</p>



Product Specification




Appendix A. LGD Proposal for system cover design.



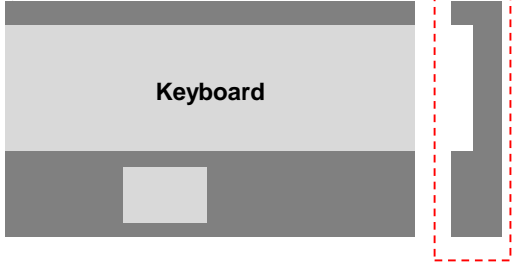

9	Check the wire position(path)
 	
Risk point	It is necessary that wire is posited out of hook, not posited near hook,.
Suggestion	If wire is posited near hook, it can be happened assemble error and panel crack during assemble front cover



Product Specification

Appendix A. LGD Proposal for system cover design.

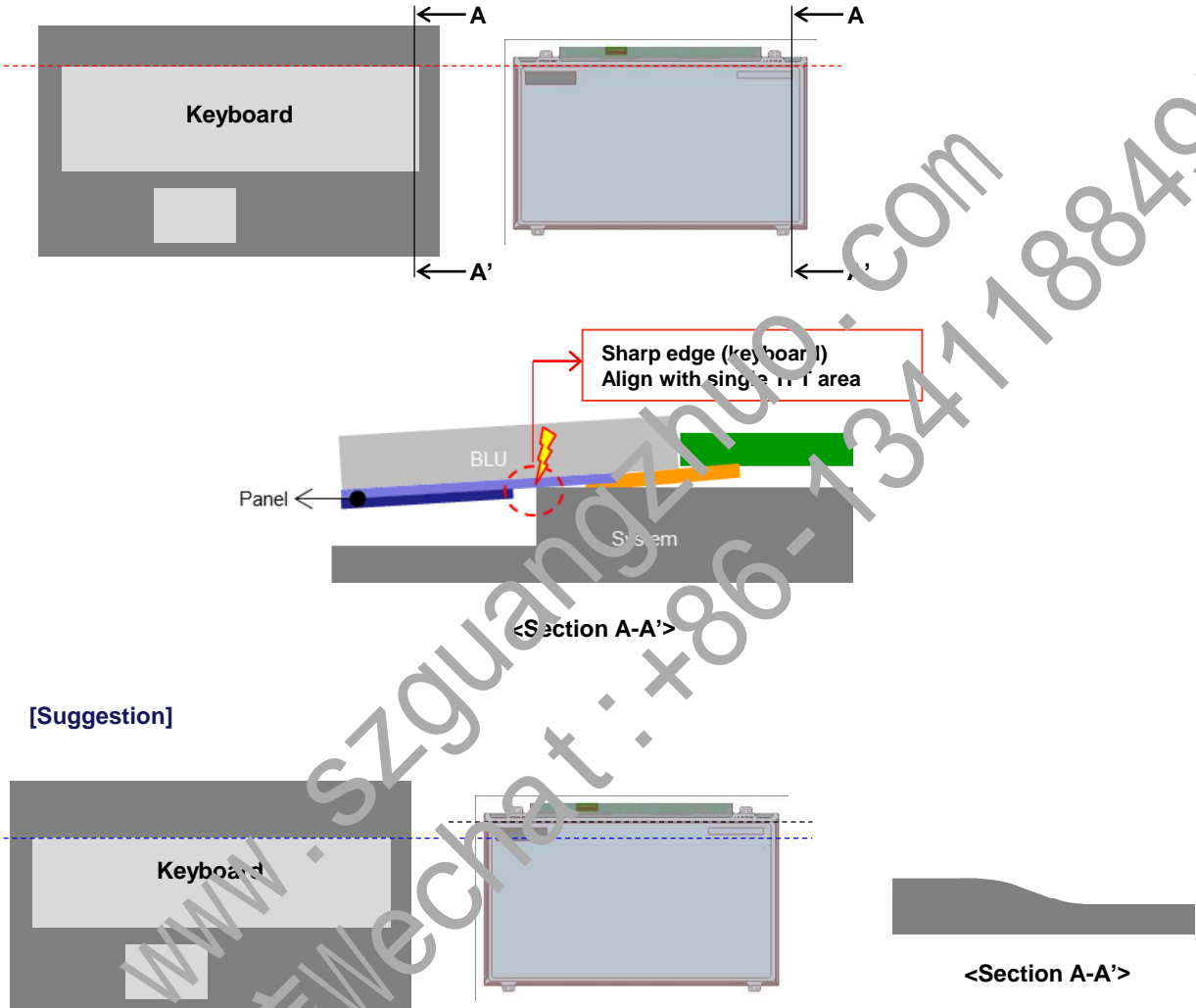
10	Check mouse pad (touch pad) depth and shape of edge
<div><div><div><p>[OK] $a \leq 0.3\text{mm}$ [Caution] $1.0\text{mm} \leq a \leq 0.3\text{mm}$ [NG] $a \geq 1.0\text{mm}$</p></div><div><div><p>OK</p><p>NG</p></div></div></div></div>	
Risk point	Mouse pad step is deep, it is caused panel crack by external load.
Suggestion	The edge shape must be smooth.

11	Check the step of keyboard area
<div><div><p>Keyboard</p></div><div><p>push</p><p>OK</p></div></div> <div><div><p>Keyboard</p></div><div><p>push</p><p>crack</p><p>NG</p></div></div>	
Risk point	The step of keyboard at the side edge of main body, it is caused panel crack
Suggestion	Keep to flat out side of keyboard.



Product Specification

Appendix A. LGD Proposal for system cover design.

12	The position and shape of keyboard step
	 <p>[Suggestion]</p>
Risk point	<p>Keyboard edge is sharp (a right angle), panel is get concentrated stress, by external force at this edge.</p> <p>Especially, keyboard edge is aligned with panel edge (single-TFT area), crack risk is seriously increase.</p>
Suggestion	<p>It is recommended that keyboard edge is posited to avoid single-TFT area.</p> <p>It is recommended that edge shape of touch pad is rounded.</p>



Product Specification

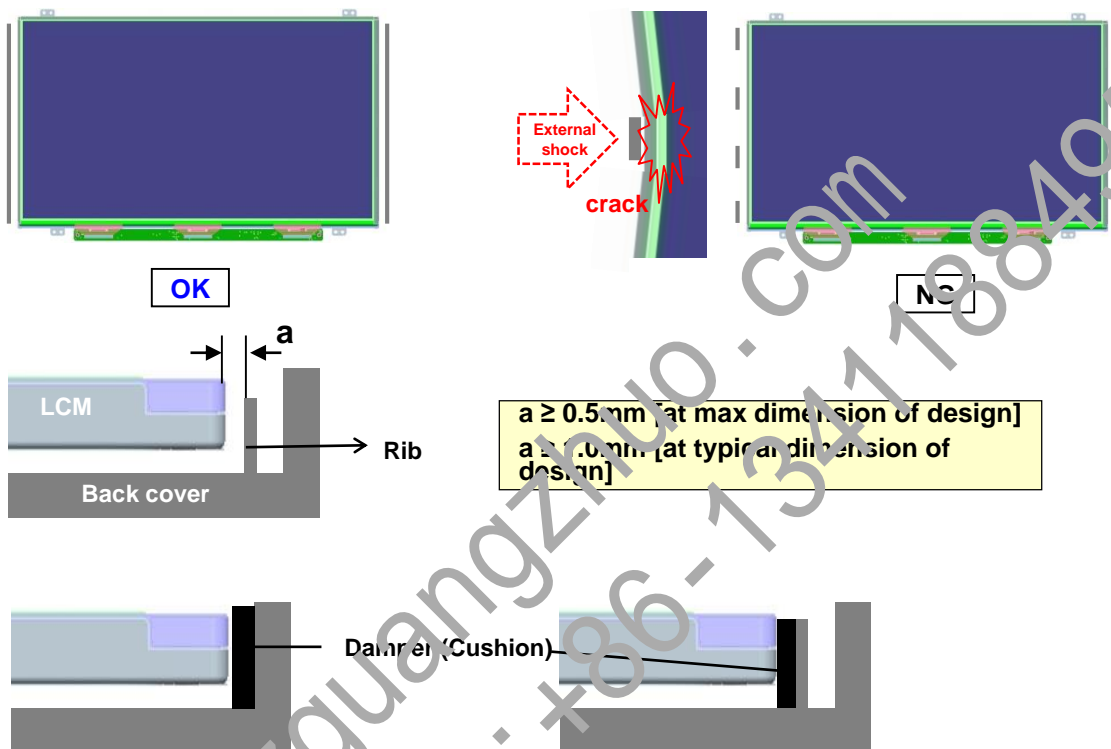
Appendix A. LGD Proposal for system cover design.

13	FPC escape figure
	<p>[mechanism of risk point]</p> <p>[Suggestion]</p> <p>[mechanism of Improved effect]</p> <p>There is not interfered [a]</p> <p>There is not interfered [a]</p> <p>< Notebook type ></p> <p>Suggestion : $\geq 1.0\text{mm}$ (at max LCM dimension)</p>
Risk point	<p>FPC is easily cracked by interference between FPC and frame during repetitive external shock or vibration.</p> <p>It is also happened when gap between is exist.</p>
Suggestion	<p>FPC crack can be improved by add escape figure at middle frame</p> <p>The gap is recommended to keep more than 1.0mm</p>



Product Specification

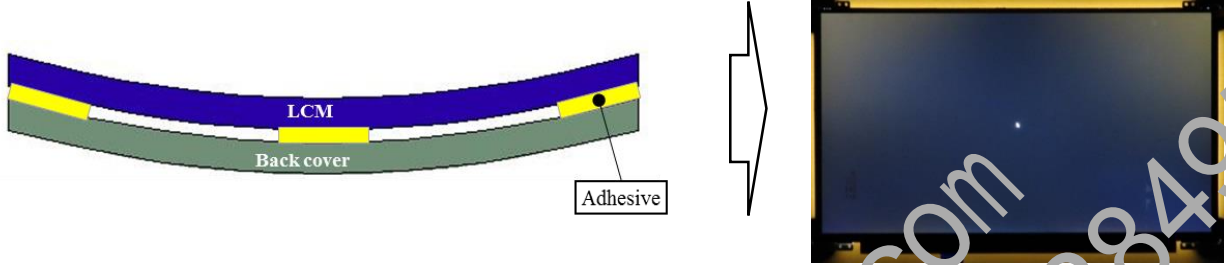
Appendix A. LGD Proposal for system cover design.

14	Back cover rib / wall (path & gap)
	 <p>OK</p> <p>External shock</p> <p>crack</p> <p>NO</p> <p>LCM</p> <p>Back cover</p> <p>Rib</p> <p>a</p> <p>a ≥ 0.5mm [at max dimension of design] a ≥ 1.0mm [at typical dimension of design]</p> <p>Damper (Cushion)</p>
Risk point	Gap is too small and rib is too short, panel is easily cracked by external stress.
Suggestion	<p>Gap is must be kept more than 0.5mm(max dim.) and 1.0mm(typ dim.) .</p> <p>The figure of rib is continuous or fully long.</p> <p>“a” is not enough as narrow bezel type, add damper between LCM and system rib/wall</p>



Product Specification

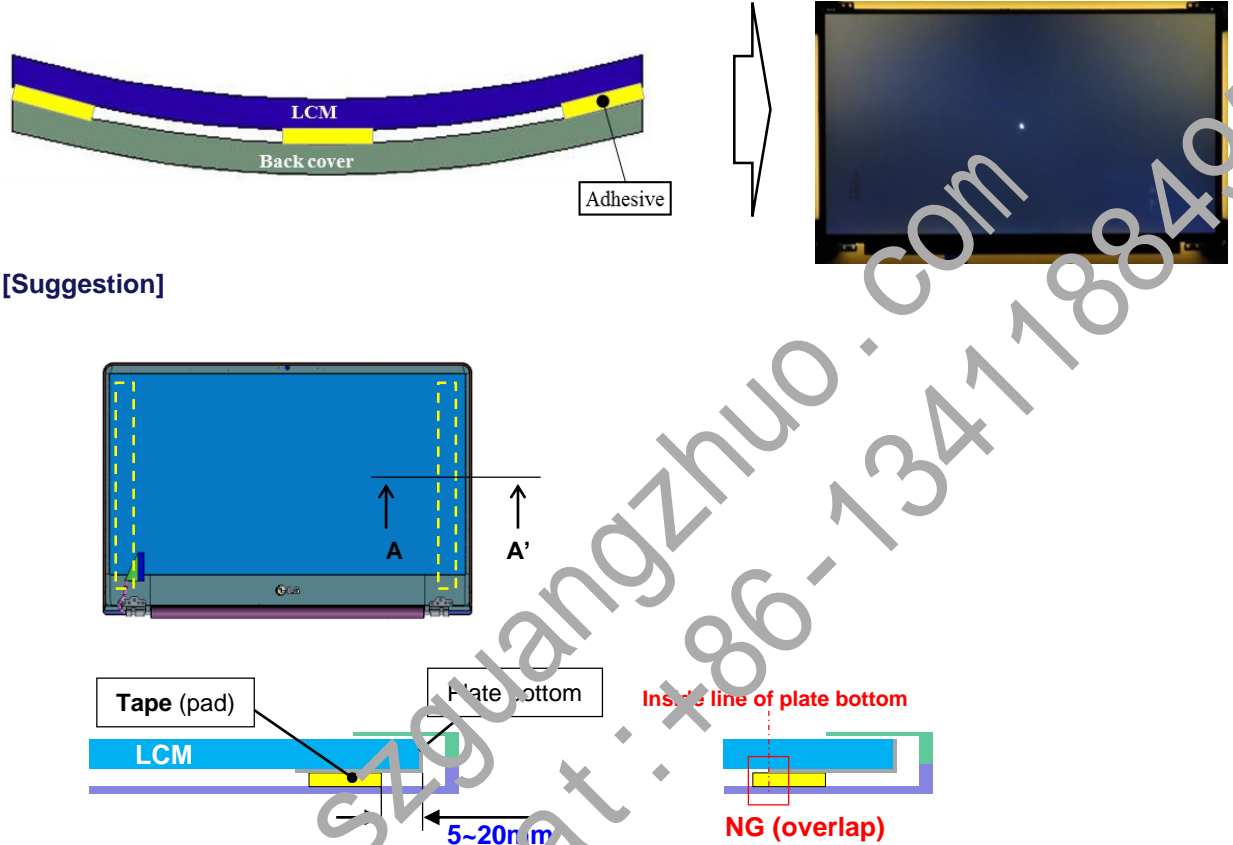
Appendix A. LGD Proposal for system cover design.

15	LCM fixing (no flange model)
<p>[Suggestion]</p> <p>Flat</p> <p>Adhesive width</p> <p>Position of pad & adhesive</p>	 <p>Back cover</p> <p>LCM</p> <p>Adhesive</p> <p>OK</p> <p>Risk</p> <p>Back cover</p> <p>LCM</p> <p>Back cover</p> <p>LCM</p> <p>LCM</p> <p>Pad or empty area</p> <p>Adhesive</p> <p>Case 1</p> <p>Pad</p> <p>Case 2</p> <p>[Mapping on back cover]</p>
<p>Risk point</p> <p>Suggestion</p>	<p>In IPS model, bended LCM, light leakage of IPS (mura) is happened.</p> <p>LCM is bended by below condition.</p> <ol style="list-style-type: none"> 1. Back cover is not flat or distorted. 2. LCM is fixed by adhesive at center area. 3. Adhesive width is too large. <p>It is recommended that back cover is flat type.</p> <p>Adhesive width need to be minimized if adhesive strength is enough.</p> <p>It is recommended that adhesive is posited at outside on back-cover.</p> <p>Pad is recommended to apply at other area.</p>



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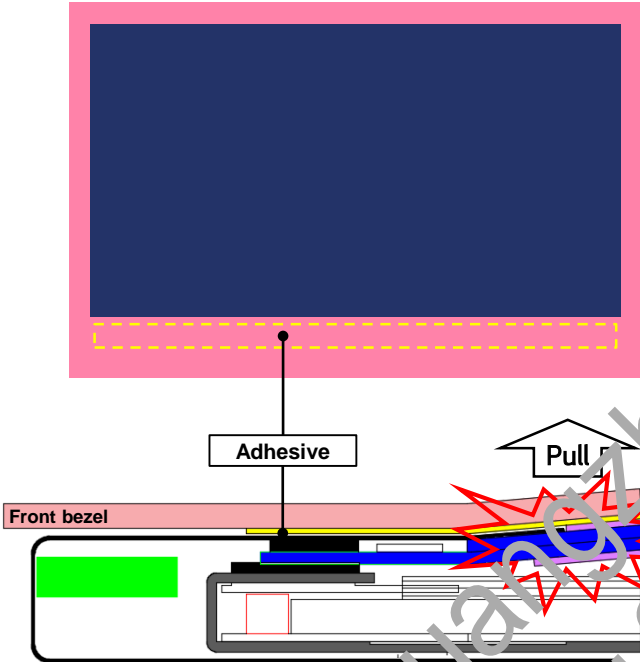

Appendix A. LGD Proposal for system cover design.

16	LCM fixing (no flange model)
<p>[Suggestion]</p> 	<p>In IPS model, bended LCM, light leakage of IPS (mura) is happened.</p> <p>LCM is bended by below condition.</p> <ol style="list-style-type: none"> 1. Back cover is not flat or distorted. 2. LCM is fixed by adhesive at center area. 3. Adhesive width is too large. <p>It is recommended to attach LCM fixing tape to the inside with reference to the outside (5~20mm). But do not overlap the pad with the inside line of the plate bottom</p>



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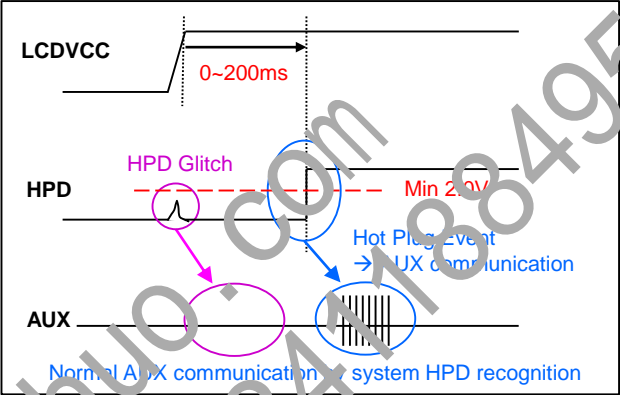
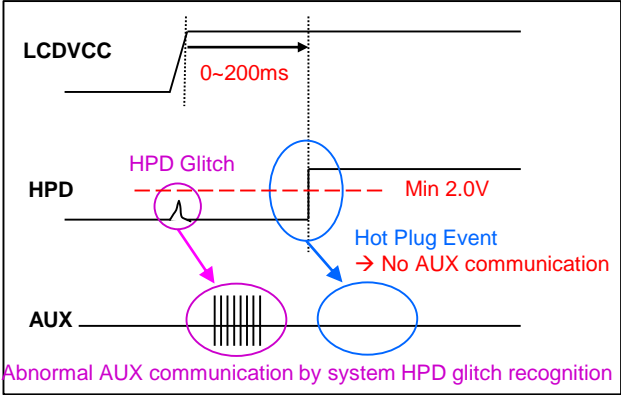
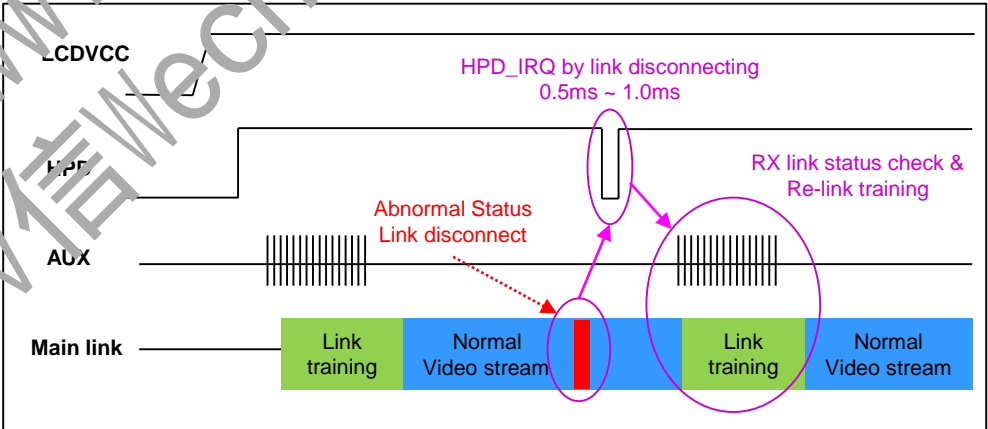
Appendix A. LGD Proposal for system cover design.

17	Parts in system main body
<div></div> <p>[Suggestion]</p> <div></div>	
Risk point	If adhesive strength behind front bezel, panel is easily broken when disassembling the front bezel.
Suggestion	Make the adhesive as weak as possible.
	Make the adhesive less than 3.0mm wide.



Product Specification

APPENDIX B. LGD Proposal for eDP Interface Design Guide

1	HPD Signal recognition
<div></div> <div>[Abnormal Communication By HPD Glitch] [Normal Communication By HPD Signal]</div>	
Define	<ol style="list-style-type: none">1. Hot Plug Detection (HPD) Threshold level of Source Device is minimum 2.0V2. HPD Unplug : HPD pulse stays low longer than 2ms. DP Tx shall wait for HPD signal to go high again.3. "HPD High" is confirmed only after HPD has been asserted continuously for 100msec.
2	IRQ (Interrupt Request) HPD Pulse Definition
<div></div>	
Define	Upon detection this "HPD IRQ Event"(0.5ms ~ 1ms), the source device must read the link / sink status field of the DPCD and take corrective action.

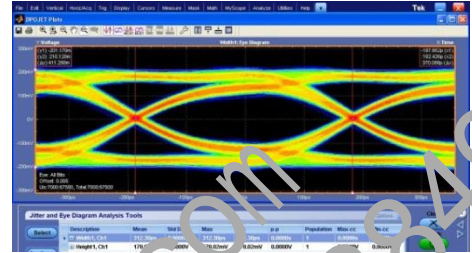
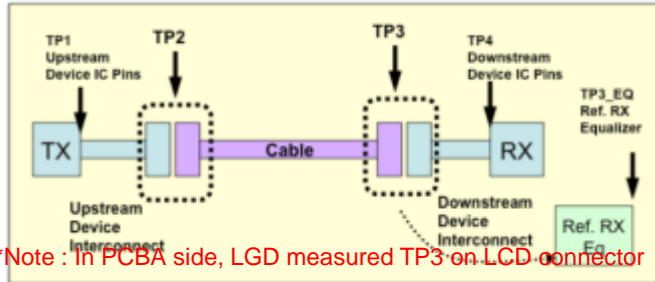


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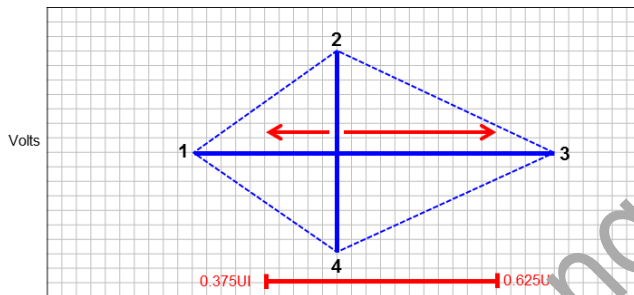
APPENDIX B. LGD Proposal for eDP Interface Design Guide

3

Main Link EYE Diagram



EYE Diagram



Point	Time(UI)	Voltage(V)
1	Any UI location (0mV)	0.000
2	$0.375 < \text{point2} < 0.625$	0.0375
3	$\text{Point1} + 0.5\text{UI}$	0.000
4	$0.375 < \text{point4} < 0.625$	-0.0375

[EYE Mask Vertices at Source Connector Pins]

Point	Time(UI)	Voltage(V)
1	Any UI location (0mV)	0.000
2	$0.375 < \text{point2} < 0.625$	0.035
3	$\text{Point1} + 0.45\text{UI}$	0.000
4	$0.375 < \text{point2} < 0.625$	-0.035

[EYE Mask Vertices at Sink Connector Pins]

Define Main Link EYE Diagram should meet TP2 and TP3 point

4

Cable Impedance management

Segment	Differential Impedance	Maximum Tolerance
Connector	90 Ω	+/- 10%
Wire management	90 Ω	
Cable	90 Ω	+/- 10%

Define Cable Impedance 90 Ω +/- 10% (81 Ω ~ 99 Ω)

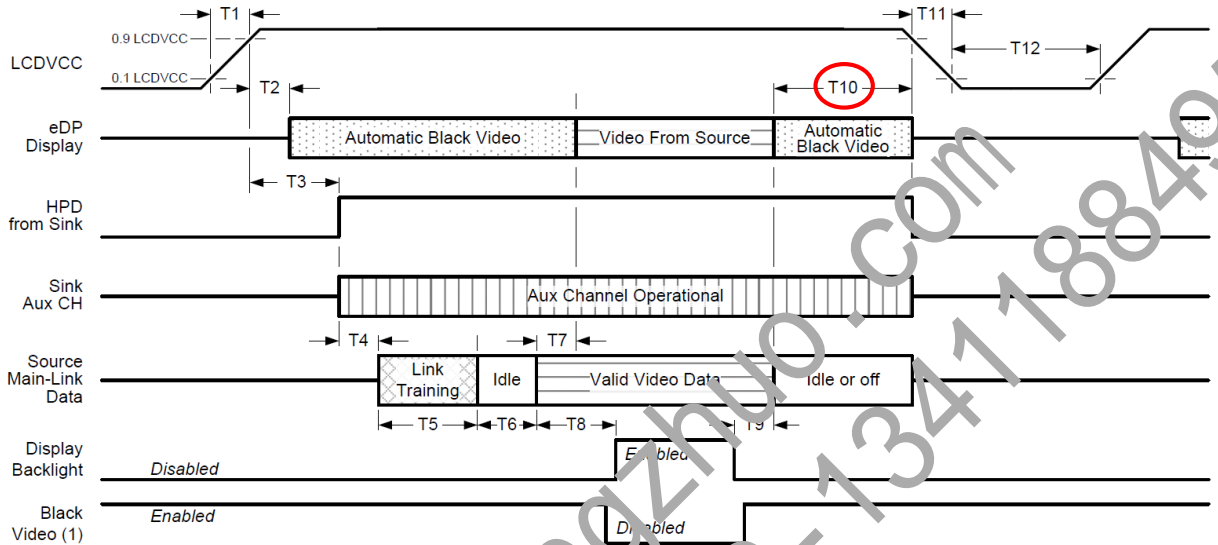


Product Specification

APPENDIX B. LGD Proposal for eDP Interface Design Guide

5

Main Link Off vs. LCD Power Off at Non-PSR

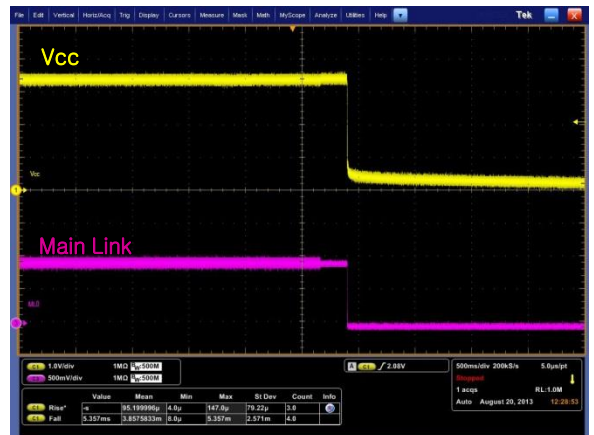


Timing Parameter	Description	Required By	Min	Max
T10	Delay from end of valid video from Source to Power Off	Source	0ms	500ms

* LGD recommend that Source must power off the LCDVCC in Main Link off like below.



[Case1. Resolution Change]



[Case2. Close the Lid]

Define

If Main Link off signal from Source, then LCDVCC must be Power Off within T10 period at Non-PSR mode

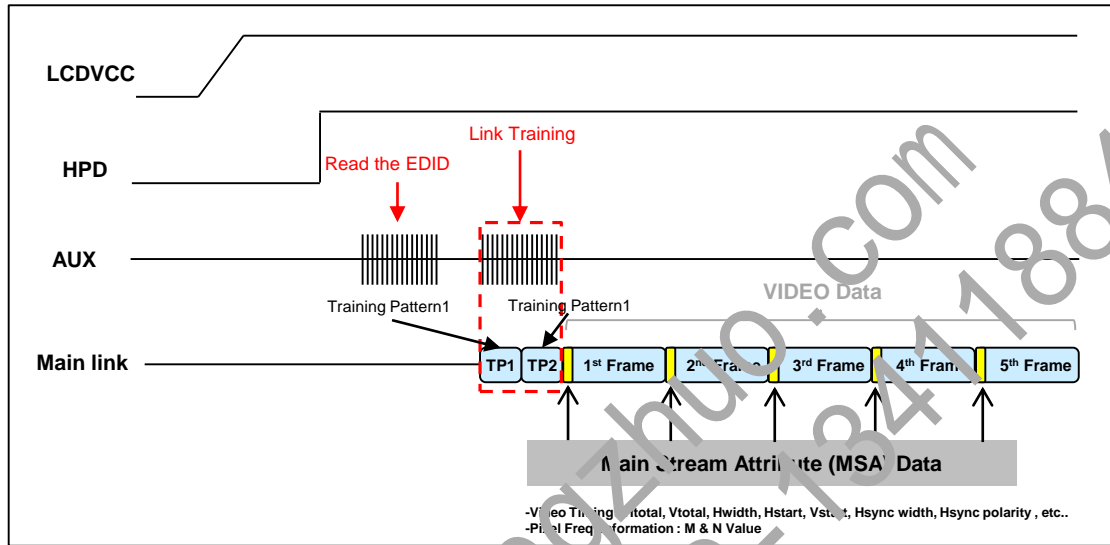


Product Specification

APPENDIX B. LGD Proposal for eDP Interface Design Guide

6

Main Link M & N value of MSA data



Define

It need to fix M& N value of MSA data output to prevent the initial abnormal M& N Value from incoming after power on.



Product Specification

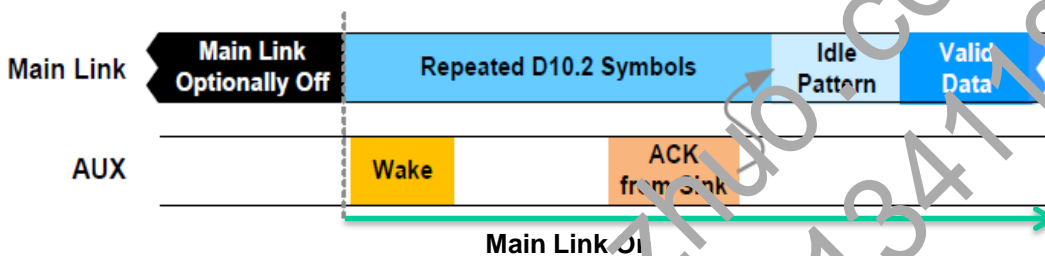
APPENDIX B. LGD Proposal for eDP Interface Design Guide

7

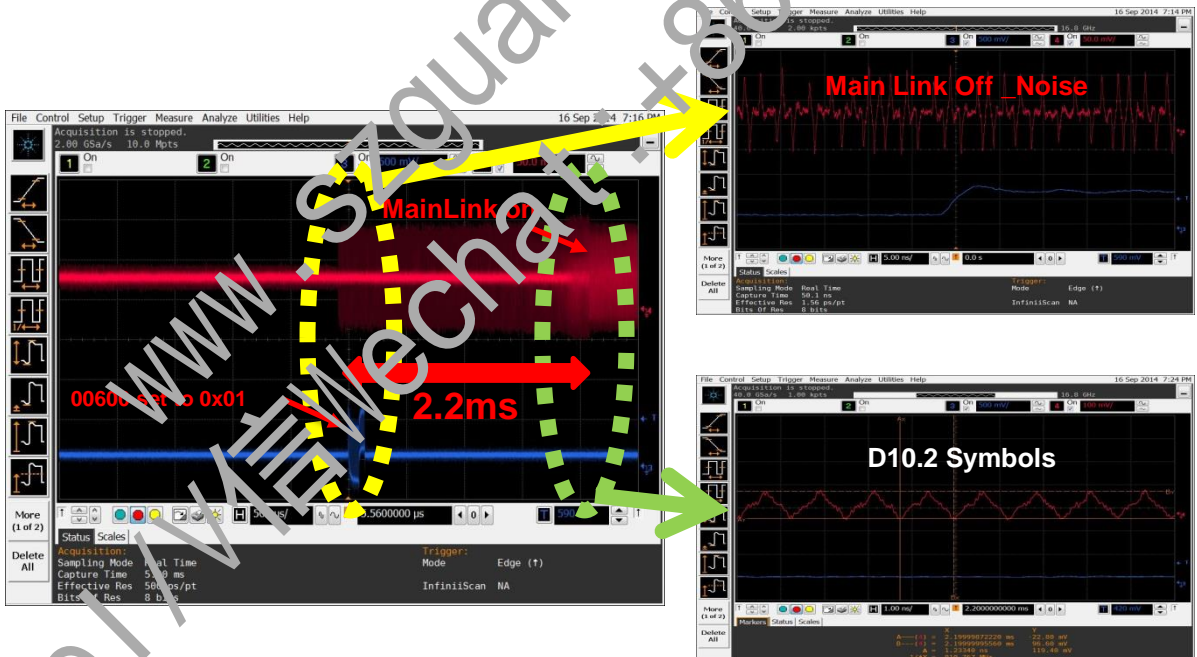
PSR Exit

If link training is not required, the Source must begin transmitting data on the Main Link prior to the wake AUX command which occurs through writing 01h to the SET_POWER & SET_DP_PWR_VOLTAGE register (DPCD Address 00600h; see DP v1.2a), as illustrated in the upper portion of Figure 6-9. This transmitted data must be a repetition of D10.2 symbols (which is the same as Link Training Pattern 1). Note the requirement above to transmit five repeats of the Idle Pattern after receiving ACK from the Sink.

PSR Exit Link Management with No Link Training



- The below waveform is the issued case



Define

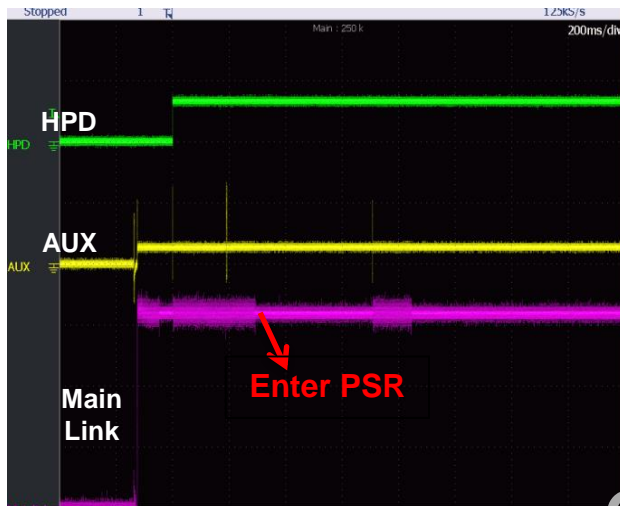
If link training is not required, the source must begin transmitting data on the ML prior to the wake AUX wake-up command.



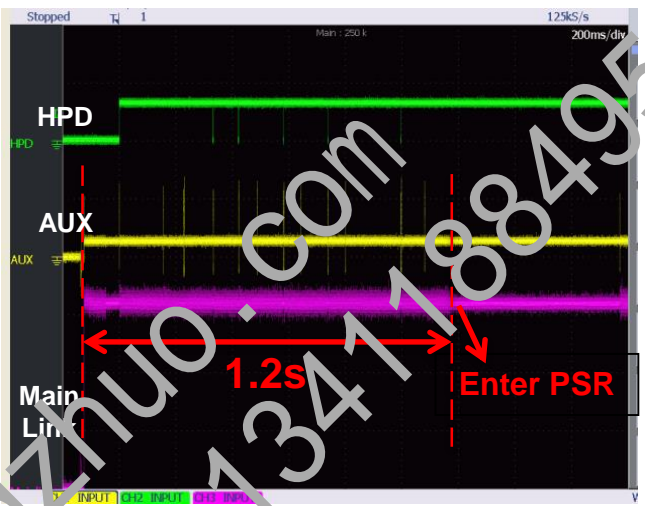
Product Specification

APPENDIX B. LGD Proposal for eDP Interface Design Guide

8

1st time PSR Entry after Power on

< Issue waveform >



< solution waveform >

1. It is found that with solution , the TCON enter the PSR timing is 1.2s delay from VCC on which avoid TCON capture the wrong data from DP link (poor link quality) and enter the BIST mode + PSR mode(black screen).
2. According to test, link is stable 800ms after VCC on.

Define

After power(Vcc) on, the DP link is not stable, so the source try to PSR entry at 800ms after Power(Vcc) on..

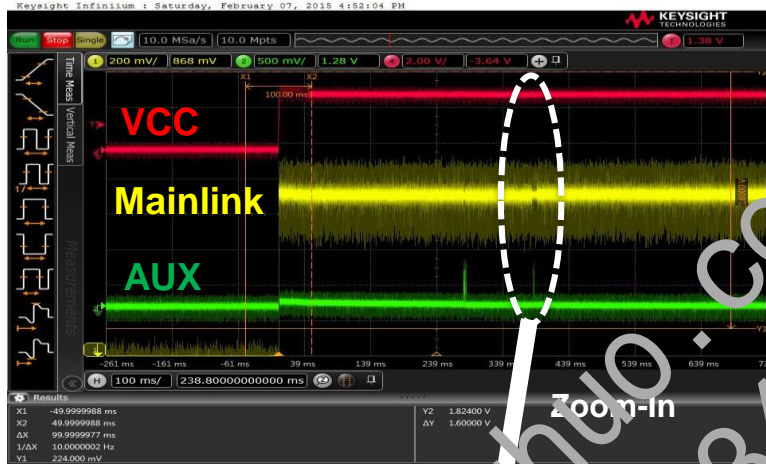


Product Specification

APPENDIX B. LGD Proposal for eDP Interface Design Guide

9

PSR Period Issue



1. When issue is happened, system go to PSR mode for very short time.
2. If PSR active period is shorter than 1frame(16.67ms), T-Con can not go to the standby mode for PSR exit.

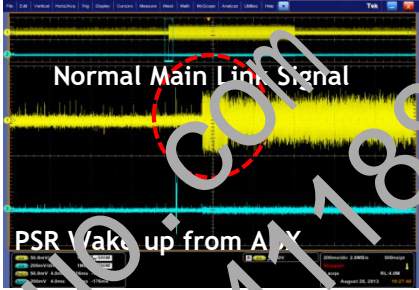
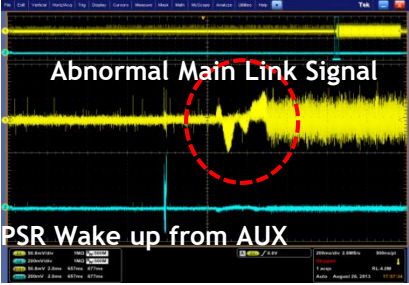
Define

When GPU go to the PSR mode, the source must hold the main link off over than 1frame.



Product Specification

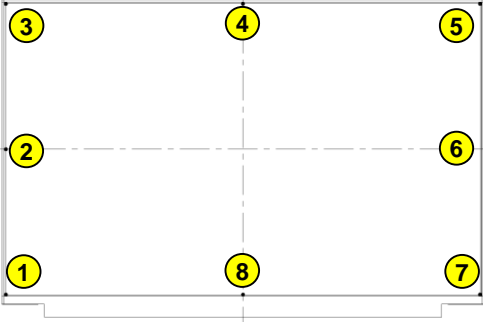
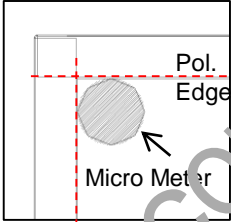
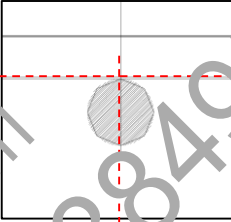
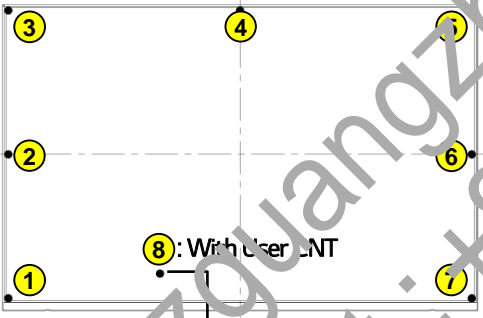
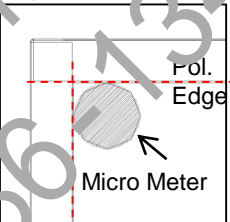
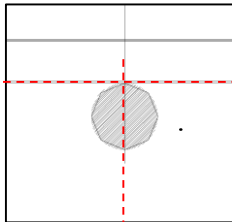
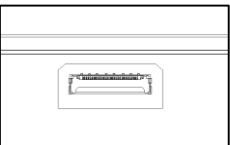


APPENDIX B. LGD Proposal for eDP Interface Design Guide

10	Main Link Noise at PSR Exit
<div><p>[Abnormal Main Link Noise]</p><p>[Normal Main Link Signal]</p></div>	
Define	Main Link Noise at PSR Exit mode can be a cause abnormal display.



Product Specification

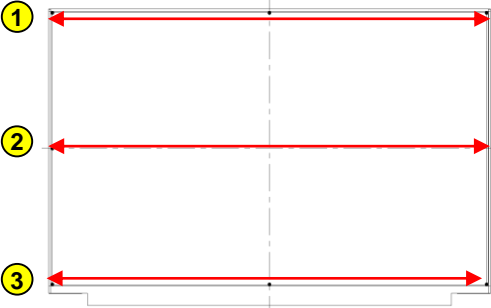
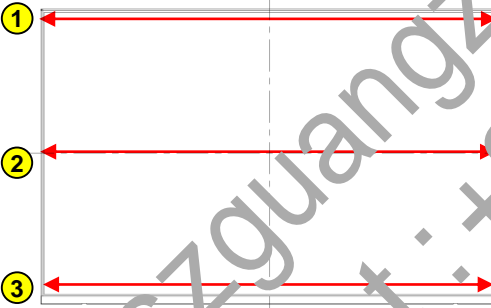
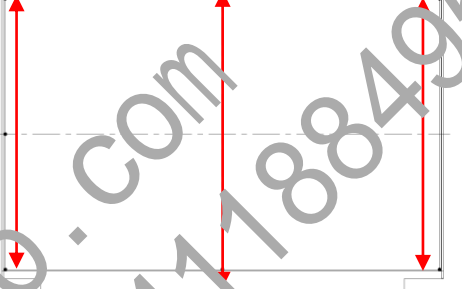
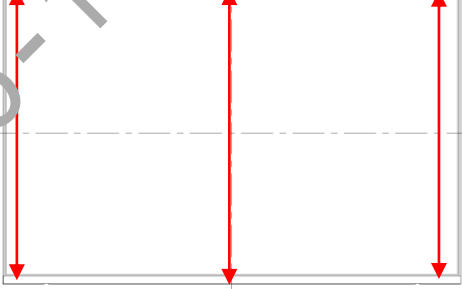
APPENDIX C. LGD Proposal for Measurement Method

1	LCM Thickness Measurement
Point	<p>[Flat Model]</p>    <p>Pol. Edge (①,③,⑤,⑦)</p> <p>LCM Center (②,④,⑥,⑧)</p> <p>[Bent Model]</p>    <p>Pol. Edge (①,③,⑤,⑦)</p> <p>LCM Center (②,④,⑥)</p>  <p>User CNT (Rear View) (⑧)</p>
Measure Tool	<p>Micro Meter</p>   <p>※ If the thickness including the User CNT part of the Bent model is located in a position where it is impossible to measure it with a micro meter, measure it with a Height Gage.</p>
Guide	<ul style="list-style-type: none"> ✓ Measure the thickness between Polarizer surface and M-Chassis on the rear of LCM ✓ Subtract Pol. protect film thickness from LCM thickness



Product Specification

APPENDIX C. LGD Proposal for Measurement Method

2	LCM Outline Dimension Measurement
Point	<p data-bbox="358 369 479 397">[Flat Model]</p>  <p data-bbox="358 778 479 807">[Bent Model]</p>  <p data-bbox="891 388 1348 417">④ ⑤ : With PCB ⑥</p>  <p data-bbox="891 803 1348 832">④ ⑤ : With FPC/COF ⑥</p> 
Measure Tool	3D Dimension Measurement
Guide	✓ Put the LCM on flat ground w/o interference on PCB rear side



Product Specification

APPENDIX D. Enhanced Extended Display Identification Data (EEDID™) 1/6

FBD



APPENDIX D. Enhanced Extended Display Identification Data (EEDID™) 2/6

FBD



APPENDIX D. Enhanced Extended Display Identification Data (EEDID™) 3/6

FBD



APPENDIX D. Enhanced Extended Display Identification Data (EEDID™) 4/6

FBD



APPENDIX D. Enhanced Extended Display Identification Data (EEDID™) 5/6

FBD



APPENDIX D. Enhanced Extended Display Identification Data (EEDID™) 6/6

FBD